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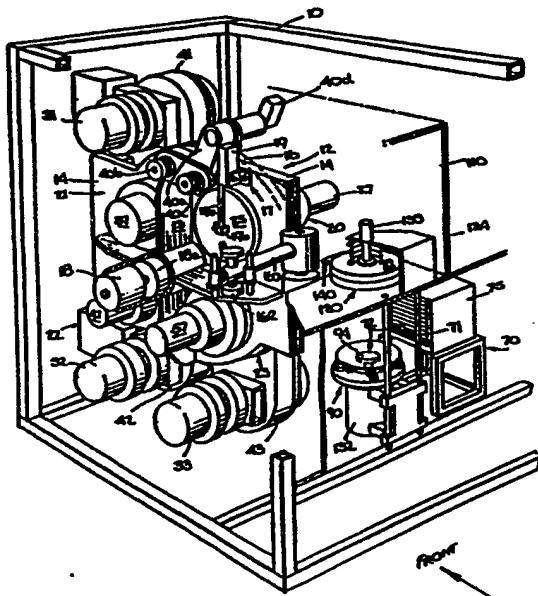
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## 54 Method and apparatus for handling and processing wafer like materials.

57 The apparatus comprises a plenum or main chamber which is divided into two chamber halves. A rotatable index plate is disposed in the chamber. An article to be processed is inserted into a load-lock station formed in the main chamber. After the article is inserted into the load-lock, it is engaged by an article holding device mounted in a position of the rotatable index plate. The index plate is then rotated to a second station, at which a process can be performed upon the substrate, for example, an etching or sputtering process. The process is performed in a processing chamber which is fully isolated from the main chamber and other processing chambers. After rotation by one position, a processed substrate is removed from the load-lock and a new substrate inserted into the load-lock for processing. After a process step is carried out on a substrate, the index plate is again rotated to the next station where another process or removal through the load-lock may be performed.



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METHOD AND APPARATUS FOR HANDLING  
AND PROCESSING WAFER-LIKE MATERIALS

1       CROSS REFERENCE TO RELATED APPLICATIONS

2             This application is related to the following co-  
3             pending applications assigned to the assignee of this  
4             application:

5             Serial No. \_\_\_\_\_, filed \_\_\_\_\_, entitled METHOD AND  
6             APPARATUS FOR HANDLING AND PROCESSING WAFER-LIKE MATERIALS;  
7             Serial No. \_\_\_\_\_, filed \_\_\_\_\_, entitled IMPROVED CATHODE  
8             AND TARGET DESIGN FOR A VACUUM SPUTTERING APPARATUS;  
9             Serial No. \_\_\_\_\_, filed \_\_\_\_\_, entitled APPARATUS FOR  
10             IMPROVING THE UNIFORMITY OF ION BOMBARDMENT IN A MAGNETRON  
11             SPUTTERING SYSTEM.

12       BACKGROUND OF THE INVENTION

13             The present invention relates to a method and  
14             apparatus for handling and processing wafer-like materials. In  
15             particular, the invention relates to a method and apparatus for  
16             handling and processing thin wafers, such as semiconductor  
17             substrates. The apparatus of the present invention can be used  
18             in systems for such purposes as etching of semiconductor wafer  
19             substrates and sputtering of deposits on such substrates.

20             Known designs for wafer processing machines allow  
21             wafers to be processed in vacuum environments. Generally, it  
22             is often necessary to perform sequentially more than one  
23             process on a substrate. For example, it may be necessary,  
24             after the wafer is introduced into the vacuum environment, to  
25             etch the wafer for preparing a surface for subsequent process  
26             steps. The next step may be the sputtering of a first metallic  
27             layer on the substrate and a further sputtering deposition step  
28             or steps may then follow. In each case, different gases may be  
29             introduced into the chamber for the different sputtering steps  
30             and different cathode target materials are used, depending on

the material to be deposited onto the substrat . Accordingly, different gaseous and plasma conditions are present for the different process steps. Generally, the prior art devices cannot allow simultaneous processing by different processes using different gaseous atmospheres of more than one wafer at a time, because once wafers are introduced into the vacuum chamber, only that particular process using that particular gas can be performed on the wafers in the chamber. If more than one process is carried out simultaneously on different wafers using these apparatus, cross contamination of the vapors and gases from the different processes may occur. Accordingly, it is not possible in these prior art arrangements to process more than one wafer at a time if different processes using different gases are to be performed upon the wafers. Thus, for example, in these priorart machines which have a plurality of processing stations, if it is desired to operate with, for example, a first gas on a first of the wafers and a second gas on a second wafer, such would not be possible simultaneously. Instead, the entire vacuum chamber would have to be purged of the first gas and the second gas introduced before the second wafer could be processed. Additionally, if a process step is to be performed on only some, but not all, of the wafers in the chamber, because all wafers are exposed to the same environment, there is the possibility of contamination of those wafers which are not being processed.

Furthermore, it is also important that the wafers be processed without transfer of the wafer between different handling mechanisms once in the vacuum chamber. Generally, the wafers to be processed in apparatus of the present invention are fragile, and to avoid particulate formation or breakage, it

1       is preferabl   to avoid transfer of the wafer between diff rent  
2       transfer mechanisms.

3             Additi nally, in wafer pr c ssing machinery,  
4       especially machinery employing sputtering devices, it is  
5       necessary to change cathodes and targets of the sputtering  
6       devices, for example, to replace a target which has been  
7       substantially used. The cathodes in sputtering equipment—  
8       generally include means for providing electromagnetic fields  
9       around the target of a particular orientation and a target of  
0       the material to be sputtered which is biased at high voltages  
1       with respect to the support structure and the substrate upon  
2       which the deposits are made. This causes the material of the  
3       target to vaporize into a plasma and be deposited upon the  
4       substrate. Where it is desired simultaneously to process a  
5       plurality of substrates in different gaseous environments, it  
6       is convenient to be able to replace only that particular target  
7       which requires replacement without disturbing the controlled  
8       environments in other process chambers in which the other  
9       substrates are disposed.

0       SUMMARY OF THE INVENTION

1             Accordingly, it is an object of the present invention  
2       to provide a wafer processing machine which allows simultaneous  
3       processing of a plurality of wafer-like articles under  
4       different environmental conditions.

5             It is furthermore an object of the present invention  
6       to provide a processing apparatus for wafer-like articles which  
7       eliminates possibilities of cross contamination of the articles  
8       being processed.

9             It is yet another object of the present invention to  
0       provid   an apparatus for pr cessing waf r-like articles in a

1           vacuum environment.

2           It is yet a further object of the present invention  
3           to provide an apparatus for processing wafer-like articles  
4           having a main vacuum chamber used for transferring the article  
5           between isolatable process chambers wherein the process steps  
6           are carried out.

7           It is furthermore an object of the present invention  
8           to provide a processing apparatus for wafer-like articles which  
9           eliminates particulate formation or breakage of the articles by  
10          preventing transfer of the article, once in the controlled  
11          vacuum environment, between different transfer mechanisms.

12          It is yet another object of the invention to provide  
13          a processing apparatus for wafer-like articles which insures  
14          optimum cleanliness of the articles being processed.

15          It is still yet a further object of the present  
16          invention to provide a processing apparatus for wafer-like  
17          articles wherein, when necessary to replace that part of the  
18          apparatus which requires replacement, for example, a cathode  
19          target, it is not necessary to shut down the entire machine or  
20          to disturb the controlled environments in other parts of the  
21          apparatus which do not require the replacement of a particular  
22          part.

23          It is yet still a further object of the invention to  
24          provide a processing apparatus for wafer-like articles having  
25          the ability to allow articles to be processed in parallel and  
26          wherein an article can be subjected to a selected one of a  
27          plurality of processes.

28          The above and other objects are achieved according to  
29          one aspect of the present invention by apparatus for  
30          transporting a wafer-like article and subjecting the article to

1 at least one process step comprising means defining a first  
2 chamber maintained substantially continuously at a vacuum or  
3 pressure level, aperture means in the first chamber through  
4 which an article to be subjected to the process step can be  
5 introduced into the first chamber, means in the first chamber  
6 for receiving and holding the article, means for moving the  
7 article held by the receiving and holding means substantially  
8 in a plane of movement to a position in the first chamber  
9 adjacent where the process step is to be performed on the  
10 article, movable means for isolating the second chamber from  
11 communication with the first chamber while the process step is  
12 performed on the article and for thereafter opening the second  
13 chamber to the first chamber so that the second chamber is in  
14 communication with the first chamber after the article has been  
15 subjected to the process step, the receiving and holding means  
16 remaining in contact with the article during the performance of  
17 the process step, and means for removing the article from the  
18 first chamber after the article has been subjected to the  
19 process step.

20 In the preferred embodiment, the moving means  
21 comprises rotatable plate means disposed in the plane of  
22 movement and the means for removing the article comprises the  
23 aperture means through which the article is also inserted into  
24 the first chamber.

25 In a preferred embodiment, the receiving and holding  
26 means comprises first means coupled to the plate means and  
27 defining an inner open area, first resilient means coupling the  
28 plate means and the first means, second means disposed in the  
29 inner open area and coupled to the first means, the second  
30 means defining a further area contained within the inner open

1 area for receiving the article, and second resilient means  
2 coupling the second means to the first means.

3 According to the invention, the first means comprises  
4 sealing surfaces on first and second surfaces thereof, and the  
5 movable means comprises closure means movable toward and away  
6 from one of the first and second surfaces and having a surface  
7 for engaging in sealing relationship with the one of the first  
8 and second surfaces of the first means, the means defining the  
9 first chamber having a further surface for engaging in sealing  
10 relationship with the other of the first and second surfaces of  
11 the first means, the first resilient means allowing the closure  
12 means to bias the other of the first and second surfaces of the  
13 first means against the further surface of the means defining  
14 the first chamber in a direction substantially perpendicular to  
15 the plane of the plate means, whereby when the closure means  
16 engages the one of the first and second surfaces and the other  
17 of the first and second surfaces engage the further surface,  
18 the second chamber is sealed from the first chamber.

19 Preferably, the article comprises a circular wafer, the first  
20 means comprises first ring-shaped member means, the second  
21 means comprises second ring-shaped member means and the first  
22 and second resilient means comprise arcuate flat spring means.

23 Preferably, the closure means comprises cup-shaped  
24 means with the surface for engaging in sealing relationship  
25 comprising a rim of the cup-shaped means. Additionally, it is  
26 preferable that the second means is removably coupled to the  
27 first means by detent means so that it can be removed from the  
28 first means when necessary, for example, for cleaning purposes.

29 The second ring-shaped means preferably includes an  
30 edge along at least a part of an inner periphery thereof

1 extending into the further area against which peripheral  
2 portions of the article can be received, and clamping means are  
3 provided comprising means disposed on the second means movable  
4 so that a portion thereof can be moved into a position  
5 extending over at least a part of the further area defined by  
6 the inside of the second means. Preferably the clamping means  
7 is rotatably movable over at least a part of the further area  
8 defined by the inside of the second means.

9 In a preferred embodiment, the rotatable plate means  
10 comprises disk means rotatably movable in the first chamber  
11 about a central axis, the disk means comprising means for  
12 holding a plurality of the receiving and holding means, the  
13 means defining the first chamber comprising means for  
14 supporting a plurality of work stations at positions spaced  
15 equi-angularly and equi-distantly about the central axis.

16 Preferably, the apparatus according to the invention  
17 also includes article handling means for inserting the article  
18 to be processed into the first chamber and for removing the  
19 article after processing from the first chamber. According to  
20 a preferred embodiment, the article handling means comprises  
21 means for retrieving an article from a carrier member and for  
22 placing the article on a movable support member, first arm  
23 means for receiving the article from the movable support  
24 member, and second arm means for receiving the article from the  
25 first arm means and for inserting the article into the aperture  
26 means in the first chamber. The first and second arm means  
27 preferably are bi-directional so that they also are used to  
28 remove a processed article from the chamber and return it to  
29 the carrier member. Preferably, the first and second arm means  
30 are disposed in a third chamber isolated from the first chamber

1 and the external environment. The third chamber includes entry  
2 means for receiving an article from the movable support means,  
3 and the movable support means comprises means for engaging in  
4 sealing relationship with a sealing surface arranged around the  
5 entry means when an article is inserted through the entry  
6 means. The entry means further comprises movable sealing means  
7 disposed in the third chamber for forming a fourth chamber in  
8 the third chamber isolated from the third chamber.

9 In a preferred embodiment, the first arm means is  
10 movable in an arcuate path and the movable sealing means is  
11 movable so as to open the third chamber to the fourth chamber  
12 when the pressures in the third and fourth chambers have been  
13 substantially equalized. Preferably, the first and second arm  
14 means comprise vacuum chuck means for engaging the article.  
15 The second arm means is preferably pivotable in the first plane  
16 or a plane parallel to the first plane so that the end thereof  
17 defines an arcuate path for receiving the article at a defined  
18 position along the path and further is rotatable about a  
19 longitudinal extent of the second arm means. In a preferred  
20 embodiment, the second arm means comprises first and second  
21 vacuum chuck means, one of the vacuum chuck means adapted for  
22 receiving an article from the first arm means in the first  
23 plane or a plane parallel to the first plane and the other  
24 adapted for transferring an article to the first arm means in  
25 the first plane or a plane parallel to the first plane. The  
26 second arm means is adapted for rotating the article about the  
27 longitudinal extent of the second arm means so that the article  
28 can be inserted into the aperture means in the first chamber  
29 from the second arm means or received through the aperture  
30 means in the first chamber for transfer to the first arm means.

1       Also, in th preferred emb ciment, the second arm means  
2       includes locking and unlocking mans for engaging with the -  
3       clamping means to secure the article in th receiving and  
4       holding means or allow its removal.

5             According to a further aspect of the invention, an  
6       apparatus for holding a wafer-like article in a movable support  
7       means and for allowing movement transverse to the support means  
8       is provided comprising first means coupled to the support means  
9       and defining a first inner open area, first resilient means  
10      coupling the support means and the first means, second means  
11      disposed in the inner open area and coupled to the first means,  
12      the second means defining a second inner open area contained  
13      within the first area for receiving the article, second  
14      resilient means coupling the second means to the first means,  
15      and means disposed on the second means for securing the article  
16      disposed in the second area to the second means.

17             Preferably, according to this further aspect of the  
18       invention, the apparatus for holding a wafer-like article is  
19       disposed in a first chamber and a second chamber is in  
20       communication with the first chamber and the first means  
21       defines sealing surfaces on first and second surfaces thereof,  
22       one of the first and second surfaces being engageable in  
23       sealing relationship with a surface of a wall means of the  
24       first chamber and the other surface being engageable in sealing  
25       relationship with movable closure means for isolating the  
26       second chamber from the first chamber while a process step is  
27       performed on the article in the second chamber, the closure  
28       means comprising means movable toward and away from the article  
29       and having a further surface for engaging in sealing  
30       relationship with the other surface of the first means, the

1       first resilient means allowing the closure means to bias the  
2       one of the first and second surfaces of the first means against  
3       the surface of the wall means in a direction substantially  
4       perpendicular to the plane of the wall means when the closure  
5       means moves towards and engages the other surface of the first  
6       means, the second chamber being isolated from the first chamber  
7       when the further surface of the closure means engages the other  
8       surface of the first means and the one surface of the first  
9       means engages with the surface of the wall means.

10           Preferably, according to this further aspect of the  
11       invention, the first means comprises first ring-shaped member  
12       means and the second means comprises second ring-shaped member  
13       means, the first and second ring-shaped member means being  
14       disposed concentrically. The first and second resilient means  
15       preferably comprise flat arcuate spring means.

16           According to this further aspect of the invention,  
17       the apparatus further comprises backing means coupled to the  
18       closure means and disposed in an area defined by the inside of  
19       the closure means for coming into close proximity with a  
20       surface of the article. The second resilient means comprises  
21       means for allowing the article to move substantially  
22       perpendicularly to a plane in which the first means is disposed  
23       when the backing means comes into close proximity with the  
24       article.

25           According to yet a further aspect of the present  
26       invention, apparatus for transporting a wafer-like article  
27       between first and second locations is provided comprising  
28       carrier means at the first location for supporting a plurality  
29       of the articles, means for retrieving an article from the  
30       carrier means and for placing the article on a movable support

1 means, th movable support means comprising means for  
2 transferring the article to a first intermediate position,  
3 first arm means movable in a first plane for receiving the  
4 article from said movable support means at the first  
5 intermediate position, and second arm means movable in the  
6 first plane or a plane parallel thereto for receiving the  
7 article from the first arm means at a second intermediate  
8 position and for delivering the article to the second location.

9 According to this yet further aspect of the present  
10 invention, the first and second arm means are disposed in  
11 chamber means isolated from the external environment, the first  
12 location being in the external environment and the second  
13 location being in communication with the environment in the  
14 chamber means. The chamber means preferably includes entry  
15 means for receiving an article from the movable support means,  
16 the movable support means comprising means for engaging in  
17 sealing relationship with a sealing surface arranged around the  
18 entry means when an article is inserted through the entry means  
19 by the movable support means.

20 The entry means preferably comprises movable sealing  
21 means disposed in the chamber means for defining a further  
22 chamber means between the movable sealing means and the movable  
23 support means when the movable support means engages with the  
24 sealing surface surrounding the entry means, thereby isolating  
25 the further chamber means from the chamber means.

26 According to this yet further aspect of the  
27 invention, in a preferred embodiment, the first arm means is  
28 movable in an arcuate path in a first plane and the movable  
29 sealing means is movable so as to open the chamber means to the  
30 further chamber means when the pressure in the chamber means

1 and further chamber means have substantially equalized, thereby  
2 allowing access by the first arm means to the article .  
3 Preferably, the first arm means comprises vacuum chuck means  
4 for engaging the article and the second arm means comprises  
5 means pivotable in the first plane or a plane parallel to the  
6 first plane and defining an arcuate path for receiving the  
7 article at the first intermediate position along the path and  
8 further is rotatable about a longitudinal extent of the second  
9 arm means. The second arm means preferably comprises first and  
10 second vacuum chuck means disposed at an end of the second arm  
11 means. One of the vacuum chuck means receives an article from  
12 the first arm means and transfers the article to the second  
13 location, which may be a load-lock of a vacuum chamber. The  
14 other vacuum chuck means receives an article from the vacuum  
15 chamber and transfers it to the first arm means. The second  
16 arm means rotates the articles about its longitudinal extent so  
17 that one device can be used for simultaneously holding two  
18 articles, one of which may be a processed article and the other  
19 yet unprocessed.

20 According to yet still another aspect of the present  
21 invention, an apparatus adapted for moving a wafer-like article  
22 between first and second locations is provided comprising bi-  
23 directional longitudinally extending arm means having an end  
24 movable in a first plane along a path for receiving the article  
25 at the first location along the path and for transferring the  
26 article to the second location and for receiving an article at  
27 the second location along the path and transferring the article  
28 to the first location, at least two engaging means disposed at  
29 an end of the arm means, the first and second engaging means  
30 being rotatable about the longitudinally extending arm means

1        between the first plane and any of a plurality of further  
2        planes, whereby the article can be transferred between the  
3        first and second locations by a combination of movement in the  
4        first plane and rotation about the longitudinally extending arm  
5        means. Preferably, the engaging means each comprise vacuum  
6        chuck means.

7        Preferably, the apparatus includes a carrier means  
8        for holding a plurality of articles disposed adjacent the first  
9        location and the article is subjected to a process step at the  
10      second location and either one of the first and second vacuum  
11      chuck means engages an article at the first location to be  
12      processed at the second location and the other vacuum chuck  
13      means engages an article which has been processed at the second  
14      location and returns the article to the first location.

15      Preferably, the second location comprises a vacuum chamber  
16      having an entry means defined by a load-lock door, and the  
17      apparatus further comprises means for opening the door and  
18      means in the chamber for holding an article to be processed in  
19      the chamber, the holding means including means for clamping the  
20      article thereto, the longitudinally extending arm means further  
21      comprising means for actuating the clamping means. The  
22      actuating means preferably comprises means disposed adjacent  
23      the first and second vacuum chuck means and extending  
24      perpendicularly to the longitudinally extending arm means for  
25      engaging the clamping means.

26      Preferably, the holding means comprises a plurality  
27      of clamping means and the longitudinally extending arm means  
28      includes a plurality of actuating means for engaging  
29      corresponding ones of the clamping means. Additionally, in a  
30      preferred embodiment, the clamping means comprises rotatable

1 means for clamping an article between a first surface and an  
2 extension of the clamping means, the clamping means comprising  
3 keyway means, the actuating means comprising key means for  
4 engaging with said keyway means, said key means being rotatable  
5 in two directions so as to secure the article between the  
6 extension of the clamping means and the first surface in one  
7 direction and allow the removal of the article by disengaging  
8 the extension of the clamping means from the article in the  
9 other direction.

10 Although the invention relates to apparatus for  
11 processing wafer-like articles in a vacuum atmosphere, it is to  
12 be understood that the invention could also be applied at  
13 pressures above atmospheric.

14 The above and other objects of the present invention  
15 are also achieved by methods for transporting wafer-like  
16 articles and subjecting the article to a process step and for  
17 handling wafer-like articles as will be explained in greater  
18 detail below.

19 BRIEF DESCRIPTION OF THE DRAWINGS

20 The invention will be described in greater detail in  
21 the following detailed description with reference to the  
22 drawings, in which:

23 FIG. 1 is an overall cut-away perspective view of the  
24 apparatus according to the invention;

25 FIG. 2 is a left side partially sectional view of the  
26 apparatus of FIG. 1;

27 FIG. 3 is a front sectional view of the apparatus of  
28 FIG. 1;

29 FIG. 3A is a schematic diagram of the apparatus  
30 according to the invention;

1 FIG. 4 is a more detailed front sectional view of  
2 part of the apparatus of FIG. 1, and in particular, that part  
3 of the apparatus which transfers unprocessed and processed  
4 wafers from or to holding cassettes;

5 FIG. 5 is a top sectional view of that part of the  
6 apparatus shown in FIG. 4;

7 FIG. 6 shows that part of the apparatus shown in FIG.  
8 4 and illustrates some of the steps of wafer handling before  
9 the wafer is introduced into a controlled environment of the  
0 apparatus;

1 FIG. 7 shows the same view as FIG. 6 but shows  
2 additional steps of wafer handling and insertion of the wafer  
3 into a controlled environment of the apparatus according to the  
4 invention;

5 FIGS. 8 and 9 show further top sectional views of  
6 portions of the apparatus shown in FIGS. 4, 5, 6, and 7, and,  
7 in particular, those portions of the apparatus and the steps  
8 performed thereby directed to centering the wafer on a lifting  
9 table and aligning an indexing mark disposed on the perimeter  
0 of the wafer on the lifting table;

1 FIGS. 10 and 11 are sectional views showing parts of  
2 the apparatus for transferring a wafer into and out of a  
3 controlled environment chamber, and different steps performed  
4 by such apparatus;

5 FIG. 12 shows a top view of a portion of the  
6 apparatus for handling the wafer in the controlled environment  
7 prior to or after processing of the wafer in the main chamber  
8 volume;

9 FIG. 13 is a side sectional view of a portion of the  
0 apparatus shown in FIG. 1, and in particular that portion of

1       the apparatus which relates to handling of the wafer in a  
2       controlled environment of the apparatus according to the  
3       invention;

4                 FIGS. 14 and 15 show top partially sectional views of  
5       the apparatus according to the invention illustrating steps in  
6       handling of wafers in the controlled environment before or  
7       after processing in the main processing apparatus proper;

8                 FIGS. 15A and 15B show schematically the steps  
9       involved in transferring a wafer to and from the wafer  
10      processing apparatus proper;

11                FIG. 16 is a top view of the apparatus according to  
12       the invention showing the main processing apparatus in its  
13       opened condition;

14                FIG. 17 is a horizontal sectional top view through  
15       the main processing apparatus of the invention taken through  
16       section lines 17-17 of FIG. 2;

17                FIG. 18 is the same view as FIG. 17 but shows the  
18       apparatus during a different step in the processing of a wafer;

19                FIG. 19 is a more detailed vertical sectional view of  
20       a portion of the apparatus shown in FIG. 18 taken through  
21       section lines 19-19 of FIG. 2;

22                FIGS. 20 and 21 show partial sectional views of  
23       portions of the apparatus for transferring a wafer to and from  
24       the main processing portion of the apparatus;

25                FIG. 22 is a detailed sectional view through a  
26       portion of the main processing apparatus showing one processing  
27       station according to the apparatus of the invention taken  
28       through section lines 22-22 of FIG. 17;

29                FIG. 23 is a sectional view like that of FIG. 22  
30       showing a different step in the processing of a wafer;

1 FIG. 24 is a front view of the means for holding a  
2 wafer in a rotatable index plate of the main processing  
3 apparatus of the invention;

4 FIG. 25 is a right side view of the apparatus  
5 according to the invention;

6 FIG. 26 is a cut away right side view showing the  
7 interior of the main processing apparatus according to the  
8 invention; and

9 FIG. 27 is a rear view of the apparatus according to  
10 the invention.

11 DETAILED DESCRIPTION

12 With reference now to the drawings, FIG. 1 shows a  
13 perspective view of the apparatus according to the invention.  
14 The front of the apparatus is considered to point to the right.  
15 The apparatus comprises, generally, a frame 10 to which is  
16 mounted a chamber 12, the chamber comprising two approximate  
17 half sections 14 and 16. The chamber includes a rotatable  
18 index plate 15, shown in greater detail in FIG. 26, which is  
19 driven by a motor 18 through a sealing member 18a, which may  
20 comprise a ferrofluidic sealing member. Each of the chamber  
21 halves 14 and 16 are reinforced by reinforcing structures 13  
22 and 13a, respectively. See FIG. 25. Chamber 12 halves 14 and  
23 16 define a main plenum area 12a, shown in greater detail in  
24 FIG. 26. Attached to each of the half sections 14 and 16 of  
25 chamber 12 and disposed at equal angular intervals about the  
26 center of chamber 12 are the respective portions of four work  
27 stations 20, 21, 22 and 23. Station 20 comprises a load-lock  
28 station for the entry and removal of processed or unprocessed  
29 articles and stations 21, 22 and 23 comprise processing  
30 stations wherein various processing steps, such as etching and

1 sputtering, may be carried out. In each work station, a  
2 different step may be carried out upon a substrate held by the  
3 rotatable index plate 15. Different processes may be  
4 simultaneously performed on different substrates at the  
5 different stations. In particular, station 20, which comprises  
6 the load-lock station, allows substrates to be inserted into or  
7 removed from the chamber 12 via a load-lock door 25 actuated by  
8 associated door operating mechanism 19, to be explained in  
9 greater detail later. Station 21 comprises a station wherein,  
10 for example, the substrate may be cleaned or etched to prepare  
11 it for further processing in stations 22 and 23, which may, for  
12 example, comprise sputtering stations wherein metallic layers  
13 are deposited on the substrate. Once a substrate has been  
14 rotated in the direction shown by arrow 17 through stations 20  
15 to 23, it is then rotated further to complete a cycle of  
16 rotation to station 20, where the processed substrate is then  
17 removed through load-lock door 25. The apparatus allows four  
18 substrates to be disposed within the machine at any one time,  
19 and three different processes may be performed at stations 21,  
20 22 and 23 on three different substrates simultaneously.  
21 Although four work stations are shown in the illustrated  
22 embodiment, a lesser or greater number of work stations could  
23 be provided by suitable modification of the apparatus.

24 The apparatus further includes a number of vacuum  
25 pumps 31, 32, 33 and 40d, which may be cryogenic vacuum pumps,  
26 for example, for providing the proper final vacuum levels in  
27 each of the volumes of the processing stations 21, 22 and 23  
28 and load-lock station 20, respectively. As will be explained  
29 later, the apparatus of the invention allows the work station  
30 volumes to be isolated from the main chamber volume 12a during

0 244 951

1 processing. Vacuum pumps 31, 32, 33 and 40d are coupled to the  
2 respective stations by respective manifold members 41, 42, 43  
3 and 40a. Before cryogenic pumps 31, 32, 33 and 40d are  
4 activated, separate mechanical vacuum pumps connected to  
5 suitable fittings 33a, 33b, 33c, and 33d are activated to  
6 evacuate the respective chambers to a level close to the  
7 desired vacuum level. See FIG. 25. Cryogenic pumps 31, 32, 33  
8 and 40d then are activated to bring the vacuum down to the  
9 desired levels. As shown in FIG. 25, fittings 33a, 33b and 33c  
10 include suitable valve members 33e, 33f and 33g, respectively,  
11 for disconnecting the mechanical vacuum sources from the  
12 respective processing chambers 21, 22 and 23, respectively.

13 Each of stations 20, 21, 22 and 23 includes a first  
14 section mounted on chamber half 14 and a second opposing  
15 portion mounted on chamber half 16. This is shown most clearly  
16 when viewed in conjunction with the top views of FIGS. 14 and  
17 15, in the side views of FIGS. 2 and 26 and in the rear view of  
18 FIG. 27. As shown in FIGS. 14 and 15, chamber half 14 includes  
19 the load-lock door 25 at station 20, shown opened in FIG. 15  
20 and closed in FIG. 14. The rear portion 16 of chamber 12 at  
21 station 20 includes a front-plane device 27, the purpose of  
22 which will be explained in greater detail below. At station  
23 21, which, in the illustrated embodiment, is an etching  
24 station, but may be a sputtering station, e.g., a back-plane  
25 device 37 is attached to chamber half 14, and chamber half 16  
26 has attached thereto manifold 41 and pump 31, which overlaps  
27 the top of the chamber 12. Back-plane device 37 is similar to  
28 front-plane device 27. At station 22, which may comprise a  
29 sputtering station, a further back-plane device 47 is provided,  
30 which may be disposed directly below the back-plane device 37.

1 This can be seen most clearly in FIGS. 1 and 2. The chamber  
2 portion 16 as shown in FIG. 1 and FIG. 25, has mounted thereto  
3 manifold 42 and pump 32, which extends below the chamber 12,  
4 and which cannot be seen in FIG. 14. At station 23, which also  
5 may be a sputtering station like station 22, chamber half 14  
6 comprises a further back-plane device 57 and chamber portion 16  
7 has mounted thereto manifold 43 and associated vacuum pump 33,  
8 as shown in FIG. 1 and FIG. 25. Again, vacuum pump 33 is  
9 disposed below the chamber 12 via the manifold 43. The two  
10 chamber halves 14 and 16 are hinged together at 425 and a  
11 locking mechanism, e.g., a screw fastener, is provided at 427.  
12 See FIG. 25. At least one seal 426 is provided, e.g., O-ring  
13 seals as shown in FIG. 26 for sealing the two chamber halves  
14 together. FIG. 16 shows the two chamber halves in the opened  
15 position. As shown, the various vacuum pumps and manifolds  
16 open together with chamber half 16. Also, as shown in FIG. 18  
17 and 27, each of the manifolds define a door which is hinged at  
18 380, allowing access to the interior of the work station  
19 without requiring opening of the main chamber 12.

20 A manifold 40a is attached to chamber half 14.  
21 Manifold 40a allows vacuum from a main cryogenic vacuum pump  
22 40d to be supplied to main chamber volume or plenum 12a and to  
23 load-lock station 20, as necessary. Before pump 40d is  
24 activated, a mechanical vacuum pump (not shown) is utilized to  
25 bring the vacuum down in the plenum 12a or the load lock 20 to  
26 a specified vacuum level close to the desired final level. A  
27 fitting 33d is provided for this purpose. See FIG. 25. Pump  
28 40d then is used to provide the final desired vacuum level. As  
29 will be explained later, manifold 40a includes a valve 40b  
30 which allows communication with main volume 12a, and valve 40c

1 which allows communication with the volume defined by th  
2 load-lock station 20.

3 Although not shown in the drawings suitable power  
4 supplies for biasing the cathode assemblies of the processing  
5 stations and the substrates are also provided. Furthermore,  
6 R.F. power supplies may also be provided behind the back-plane  
7 devices 37, 47, and 57 for improving step coverage desposition  
8 on the substrates.

9 As shown in the drawing figures, the apparatus  
0 includes a wafer receiving section, indicated generally at 70,  
1 a wafer alignment, centering and lift means 90, a controlled  
2 environment chamber 110 having an intermediate load-lock  
3 indicated generally at 120, a transfer arm 140 disposed in  
4 chamber 110 for receiving and delivering a wafer from or to the  
5 intermediate load-lock 120, and for transferring a wafer to or  
6 from a load-lock arm 160, which transfers a wafer, whether  
7 processed or unprocessed, to or from the main load-lock station  
8 20 of chamber 12. Receiving station 70 includes a cassette 75  
9 holding a plurality of wafers to be processed and/or wafers  
0 which have already been processed by the apparatus of the  
1 invention. A pick and place mechanism 80 transfer wafers  
2 between cassette 75 and alignment, centering and lift means 90.  
3 See FIGS. 2, 3 and 4. Two cassettes 75 and 76 may also be  
4 used. See FIG. 4. As indicated, mechanisms 80, 90, 120, 140  
5 and 160 are bi-directional, i.e., unprocessed wafers from  
6 section 70 are transferred to chamber 12 by these mechanisms  
7 and processed wafers are returned to section 70 by the same  
8 mechanisms.

9 FIG. 3A is a schematic representation illustrating  
0 the overall operation of the apparatus according to the present

1 invention. Substrates to be processed are supplied from one of  
2 two cassettes 75 or 76 into the controlled environment 110 via  
3 intermediate load-lock 120. The substrate is then transferred  
4 into load-lock 20. A sealing member, for example, load-lock  
5 door 25, isolates load-lock 20 from the controlled environment.  
6 A valve 20a is utilized to vent the load-lock to the controlled  
7 environment so that the load-lock door 25 can be opened to the  
8 controlled environment 110 to allow the substrate to be  
9 received in the load-lock 20. A mechanical pump (not shown)  
10 and cryogenic pump 40d are utilized to evacuate the load-lock  
11 20 via suitable valves including valve 40c, once load-lock door  
12 25 is closed. A sealing member A, to be described in greater  
13 detail below, seals the load-lock 20 from the plenum 12a, and  
14 opens the plenum 12 to the load-lock once the load-lock has  
15 been evacuated to the vacuum level existing in the plenum 12a.

16 As will be explained in greater detail below, the  
17 plenum 12a, defined by chamber 12, is utilized to transfer the  
18 articles to be processed from one processing chamber to  
19 another. The processing chambers are shown at 21, 22 and 23.  
20 The plenum 12a itself, however, is not utilized to perform  
21 process steps, such as sputtering or etching. Rather, the  
22 substrates are transported through the plenum and transferred  
23 to at least one of the processing chambers, where the process  
24 step is performed. In accordance with the invention, an  
25 article to be processed need not be processed serially, as the  
26 apparatus of the present invention allows an article to skip a  
27 particular process chamber, for example. Assuming that the  
28 article is to be processed in all process chambers, however,  
29 the article is isolated from plenum 12a via sealing member B  
30 and then supplied to process chamber 21. Pump 31 (and

1 associated mechanical vacuum pump) is utilized to evacuate the  
2 process chamber 21 and a valve 21a provides process gas to the  
3 process chamber 21. If further processing of the article is to  
4 occur after processing in process chamber 21, the article may  
5 be transferred to process chamber 22 through a sealing member  
6 C, as shown. Pump 32 (and associated mechanical vacuum pump)  
7 is utilized to evacuate process chamber 22 and process gas is  
8 supplied to the process chamber 22 via valve 22a. If further  
9 processing is to occur, the article may be transferred to  
.0 process chamber 23 through a sealing member D. A pump 33 (and  
.1 associated mechanical vacuum pump) is utilized to evacuate  
.2 process chamber 23 and process gas is provided to the chamber  
.3 23 via valve 23a. In the illustrated embodiment, three process  
.4 chambers are shown, although more or fewer process chambers  
.5 could be provided. After the article has been processed in  
.6 process chamber 23, it is again supplied back to the load-lock  
.7 20 via sealing member A. The article is then returned via  
.8 sealing means 25 to the controlled environment 110 and returned  
.9 to the cassettes 75 and 76.

0 Accordingly, the apparatus shown schematically in  
1 FIG. 3A allows isolation of each process chamber 21, 22 and 23  
2 from the other process chambers and also from the main plenum  
3 12a. This prevents cross-contamination between processes being  
4 performed in the different process chambers. Furthermore, the  
5 apparatus shown allows essentially random access to the  
6 different process chambers. Therefore, it is not necessary  
7 that the article to be processed enter each process chamber.  
8 Rather, the article to be processed can skip a process chamber  
9 if that particular process is not to be performed on the  
article. Additionally, the process to be performed in a

1       particular process chamber can be changed without affecting the  
2       other process chambers, because of the isolation provided by  
3       seals B, C and D which isolate each process chamber from the  
4       others and the plenum 12a.

5               Furthermore, each process chamber 21, 22 and 23 is  
6       essentially independent of the other process chambers, having  
7       its own pumps, valves, gas inlets and processing means, so that  
8       if one processing chamber ceases to function for some reason,  
9       the other chambers are not affected. The gas inlets to each  
10      process chamber are shown in FIG. 25 at 21a, 22a and 23a.

11               The structure of sealing members A, B, C and D will  
12      be described in greater detail below, and forms an important  
13      part of the invention. In the embodiment shown in the  
14      drawings, sealing members A, B, C and D comprise sealing ring  
15      members and resilient spring means which hold the article in  
16      position during processing and also provide the necessary  
17      motion and sealing action between the process chamber and the  
18      plenum 12a. Although separate sealing members A, B, C and D  
19      are shown in FIG. 3A, in an actual embodiment of the device,  
20      the same sealing member is used to seal the different process  
21      chambers once a substrate enters the plenum 12a, as the sealing  
22      members perform not only a sealing function but also hold the  
23      substrate in position during its movement in the plenum 12a.  
24      More than one substrate, can, of course, be processed in  
25      chamber 12 at one time, and accordingly, a plurality of sealing  
26      members, one of which is associated with a respective process  
27      chamber at a particular point in time, may be provided. This  
28      will be explained in greater detail below.

29               The operation of the invention will now be described  
30      in greater detail. With particular reference to FIGS. 3 and 4,

1       the apparatus of the present invention may include one cassette  
2       75 or two cassettes 75 and 76 holding a plurality of stacked  
3       wafers 72. Although the cassettes are shown to be  
4       substantially horizontal in the drawings, they may have a  
5       slight inclination from the horizontal so that the open ends of  
6       the cassettes, shown in FIGS. 1 and 3 and identified with  
7       reference numeral 71, are slightly raised from closed side 73.  
8       In this way, sliding of the wafers in the cassettes 75 or 76 so  
9       that they fall out of the open ends 71 is prevented. Cassettes  
10      75 and 76 are mounted on frames 77 and 78, respectively. A  
11      pick and place mechanism 80, which is movable in both X and Y  
12      axes, shown in FIG. 3 and more clearly in FIG. 4, is provided  
13      for retrieving unprocessed wafers from the cassettes and for  
14      inserting processed wafers into the cassettes. Pick and place  
15      mechanism 80 is driven by a motor 81 and a suitable linkage,  
16      for example, along tracks 82. Pick and place mechanism 80  
17      includes a movable arm 83 having suitable grasping mechanisms,  
18      e.g., vacuum chucks 84 and 86, disposed at ends of the arm.  
19      This is shown more clearly in FIGS. 4 and 5. Arm 83, as shown  
20      in FIG. 5, is fastened to a second cross arm 87, which is  
21      mounted to member 88, member 88 being slidable in the X  
22      direction along tracks 82. Arm 87 is slidable in a track 85 in  
23      member 88 in the Y direction. Motor 81 drives via a first  
24      screw 91 member 88 and thus arm 87 in the X direction and also  
25      via a second screw 91a or other suitable linkage in the Y  
26      direction.

27                  The sequence of operation of pick and place mechanism  
28      80 is shown in FIGS. 4 through 7. FIG. 4 shows a wafer 72 on  
29      alignment and lifting mechanism 90. The wafers may comprise,  
30      e.g., 6 or 8 inch silicon semiconductor substrates. Alignment

1 and lifting mechanism 90 includes a vacuum chuck 94. The  
2 processed wafer 72 has been removed from chamber 12 of the  
3 machine. Pick and place mechanism arm 83 is driven from its  
4 prior position, which is shown by the phantom line in FIG. 4 at  
5 92, so that vacuum chuck 84 is just below the lower surface of  
6 substrate 72 on vacuum chuck 94. Vacuum chuck 94 at this point  
7 is deactivated and vacuum chuck 84 activated, so that wafer 72  
8 is picked up by vacuum chuck 84. Arm 83 is now driven  
9 horizontally to the left and then vertically upward and to the  
10 right to the position adjacent cassette 75 at which the  
11 processed wafer is to be inserted. This is shown by the  
12 position of the arm 83 shown in phantom near cassette 73 in  
13 FIG. 4. Arm 83 is then driven further in the X-direction so as  
14 to place the substrate into a slot of the cassette. As an  
15 example, the last, or top slot of cassette 75 has been chosen  
16 in FIGS. 4 and 6. As shown in FIG. 6, once a processed wafer  
17 has been inserted into the last position in cassette 75, arm 83  
18 is driven to the left in the X direction, as shown by the arrow  
19 83a, and then vertically downward to a position adjacent  
20 cassette 76 so that an unprocessed wafer can be picked up by  
21 vacuum chuck 86. If the last position of cassette 75 had not  
22 been reached, arm 87 would have moved upward one position to  
23 retrieve the next wafer (unprocessed) in cassette 75. Assuming  
24 only processed wafers remain in cassette 75, however, arm 87  
25 traverses to cassette 76 to remove an unprocessed wafer. Each  
26 cassette 75 and 76 can at any time contain both processed and  
27 unprocessed wafers. It is not necessary that one cassette  
28 contain only processed wafers and the other cassette  
29 unprocessed wafers.

30 Assuming that a processed wafer has been placed in

0 244 951

1 the uppermost position of cassette 75, the arm 83 will travel  
2 to the left in FIG. 6 as shown, and then vertically downward to  
3 a position adjacent the sixth position from the bottom of  
4 cassette 76. (Assuming five wafers have already been removed  
5 from cassette 76 and are now in chamber 12 and on load-lock arm  
6 -- 160 -- to be explained in greater detail later.) Accordingly,  
7 arm 83 moves so that vacuum chuck 86 enters the cassette 76 to  
8 remove an unprocessed wafer therefrom. Arm 83 then moves in  
9 the X direction to the right as shown by the arrow 83b, and  
10 then moves downwardly in the vertical direction to a position  
11 adjacent the right side of the vacuum chuck 94. Vacuum chuck  
12 94 is now activated and vacuum chuck 86 deactivated.  
13 Accordingly, wafer 72 is left in the position shown by the  
14 dotted lines on top of vacuum chuck 94. Arm 83 then moves to  
15 the right to the home position 83c shown in FIG. 7, so it is  
16 out of the way of vacuum chuck 94.

17 As shown in FIG. 8, a wafer 72 may be placed on  
18 vacuum chuck 94 slightly off center from the center 95 of  
19 vacuum chuck 94. It is necessary to align the center of the  
20 substrate with the center 95 of vacuum chuck 94. Accordingly,  
21 lifting table 90 includes an aligning means comprising four  
22 radially disposed movable members 102 mounted on support 98.  
23 Radially disposed members 102 include aligning pins 109. When  
24 it is necessary to align substrate 72, vacuum chuck 94 moves  
25 vertically downward, as shown in FIG. 7. At the same time,  
26 vacuum is removed from vacuum chuck 94 and radially disposed  
27 members 102 move radially inwardly, as shown in FIG. 9, thus  
28 biasing pins 109 against wafer 72 and aligning wafer 72 with  
29 the center axis of vacuum chuck 94. The movable members 102  
30 may be guided radially on guide rods 114 or by any other

1 suitable operating mechanism. Wafer 72 may also include an  
2 indexing mark or flat spot, for example, flat spot 111. It may  
3 be necessary to align the flat spot properly on vacuum chuck 94  
4 so that the wafer is properly inserted into chamber 12.  
5 Accordingly, vacuum chuck 94 holding wafer 72 is rotated as  
6 shown by arrow 112. Proper orientation of the index mark 111  
7 may be determined by a light source and light sensor, for  
8 example, a light source 113 (See FIG. 13) disposed near the  
9 intermediate load-lock 120 and a light sensor 113a disposed on  
10 support 98. Other indexing marks can be used instead of a flat  
11 spot, for example, a small notch in the substrate 72.

12 Once the substrate has been centered and aligned,  
13 support 98 is driven along guide rails 130 and 131 vertically  
14 by a suitable actuating means 132, as shown by the phantom  
15 lines in FIG. 7. Substrate 72 is raised into a recess 122  
16 disposed in a housing 124 defining chamber 110 for maintaining  
17 a controlled environment therein. Housing 124 includes an  
18 aperture therein defined by an upstanding circular wall 126. A  
19 top seal cover 128 is movable in the vertical direction, and  
20 when in contact with upstanding wall 126, seals controlled  
21 environment chamber 110 from the outside via O-ring seals 129.  
22 Lift table support 98 includes a sealing surface 133 which  
23 seals via O-ring seal 131a with housing 124 when it engages  
24 housing 124. The operation of the load-lock thus formed is  
25 shown more clearly in FIGS. 10 and 11.

26 As shown in FIG. 10, the intermediate load-lock 120  
27 is provided in order to maintain the purity of the atmosphere  
28 in the controlled environment 110, which essentially may  
29 comprise an environment of dry nitrogen gas, as it is desired  
30 to prevent as much water vapor and other contaminants as

possible from being introduced into the main chamber 12.

Accordingly, prior to removing top seal 128, which is movable in a vertical direction as shown, nitrogen gas is introduced via a valve 134 into the volume 122. At the same time, a valve 135 is opened thereby to remove the existing atmosphere in chamber 122. Once dry nitrogen gas has been introduced into chamber 122 for a sufficient period of time and the existing atmosphere has been purged, it is necessary to adjust the pressure in chamber 122 so that it approximates the pressure in the controlled environment 110. Accordingly, a bleed valve 137 is activated to allow the pressure in controlled environment 110 to equalize substantially with the pressure in chamber 122. Once the pressure has equalized, top seal 128 is opened, as shown in FIG. 10, and transfer arm 140, which is shown in greater detail in FIG. 12, enters the opened chamber 122 and vacuum chucks 142 disposed on the transfer arm 140 end section 145 engage the wafer 72 for removing the wafer from chamber 122. See FIGS. 11 and 12. In FIGS. 11 and 12, transfer arm 140 is shown engaging wafer 72. Transfer arm 140 enters chamber 122 slightly below the level of wafer 72, and once in position, moves vertically upward so that vacuum chucks 142 engage wafer 72 and remove it from vacuum chuck 94. Alternatively, vacuum chuck 94 may be allowed to lower instead, thus dropping wafer 72 onto transfer arm 140.

FIG. 12 shows the operation of transfer arm 140 in greater detail. FIG. 12 is a top view of the transfer arm 140 and load-lock arm 160. Transfer arm 140 is pivotably mounted as shown at 147 and driven by a motor 143. See FIG. 13. Top seal cover 128 and the mechanism 133 for operating the top seal cover, which may comprise a hydraulic cylinder or other

1 activating device, are shown. See also FIGS. 1, 2 and 13.  
2 Transfer arm 140 includes a straight section 144 and a  
3 crescent-shaped section 145 having disposed thereon vacuum  
4 chucks 142. Vacuum chucks 142 may comprise a recessed groove  
5 having a square configuration leading to a vacuum source, as  
6 shown. The purpose of transfer arm 140 is to receive --  
7 unprocessed wafers from vacuum chuck 94 and deliver them to  
8 load-lock arm 160 and conversely, to receive processed wafers  
9 from load-lock arm 160 and deliver them to vacuum chuck 94.  
10 The purpose of load-lock arm 160 is to supply wafers to be  
11 processed to the load-lock station 20 of chamber 12 and to  
12 retrieve processed wafers from load-lock station 20 and deliver  
13 them to a position whereby transfer arm 140 can retrieve them  
14 to return them to vacuum chuck 94, which then eventually  
15 returns them to cassettes 75 and 76. Load-lock arm 160 is  
16 rotatable about pivot point 163 in the plane of FIGS. 14 and 15  
17 and also about an axis 167 as shown.

18 With reference to FIGS. 15A and 15B, the operation of  
19 transfer arm 140 and load-lock arm 160 will now be explained.  
20 FIGS. 15A and 15B are a schematic illustration of the positions  
21 of load-lock 20, load-lock arm 160, transfer arm 140 and  
22 intermediate load-lock top seal 128 during a complete machine  
23 cycle. In FIGS. 15A and 15B, "O" designates "open", "C"  
24 designates "closed," "U" designates "unprocessed" and "P"  
25 designates "processed." With reference to FIGS. 12, 14, 15A  
26 and 15B, the operation is as follows. Transfer arm 140 moves  
27 from the position shown in FIG. 14 at A to the position shown  
28 at B in FIG. 14, at which it receives a new wafer from vacuum  
29 chuck 94. Top seal 128 is open at this time as shown in FIG.  
30 15A(a). Transfer arm 140 continues along the arcuate path

0 244 951

1 defined by the arrows 141 to position C as shown in FIG. 14 and  
2 eventually places an unprocessed wafer up n the upper vacuum -  
3 chuck 162 of load-lock arm 160 at point D. This is shown in  
4 FIG. 15A(a). At this point load-lock 20 is closed and transfer  
5 arm 140 moves to point C in FIG. 14. Load-lock arm 160 as  
6 .. shown in FIG. 15A(b) now rotates  $180^{\circ}$  about axis 167, thus  
7 || placing the unprocessed wafer at the bottom and the processed  
8 || wafer which has already been removed from the load-lock 20 on  
9 || top. Transfer arm 140 returns to position D shown in FIG. 14  
0 || and the processed wafer is now removed by transfer arm 140 as  
1 || shown in FIG. 15A(c), and returned to the intermediate load-  
2 lock 120 as shown at FIG. 15A(d), whereby the processed wafer  
3 is returned to one of the cassettes 75 or 76. The next step,  
4 as shown in FIG. 15A(e), is the rotation of load-lock arm 160  
5  $90^{\circ}$  about axis 167 so that the unprocessed wafer faces away  
6 from the load-lock 20. Load-lock 20 now opens as shown in FIG.  
7 15A(f), and load-lock arm 160 rotates about pivot 163  $90^{\circ}$   
8 clockwise so that the empty vacuum chuck of load-lock arm 160  
9 facing load-lock 20 can retrieve a processed wafer from load-  
0 lock 20. Once a processed wafer has been engaged by the load-  
1 lock arm 160, load-lock arm 160 pivots counterclockwise  $90^{\circ}$  as  
2 shown in FIG. 15A(g). Accordingly, a processed wafer and an  
3 unprocessed wafer are now disposed upon the two vacuum chucks  
4 of load-lock arm 160 as shown in FIG. 15A(g). Load-lock arm  
5 160 now rotates  $180^{\circ}$  about axis 167 as shown in FIG. 15B(h), so  
6 that the unprocessed wafer faces the load-lock 20. Load-lock  
7 arm 160 now rotates  $90^{\circ}$  about pivot 163, and the unprocessed  
8 wafer which had been placed on the load-lock arm 160 in step  
9 15A(a), is now ins rted into load-lock 20 when load-lock arm  
0 160 pivots  $90^{\circ}$  clockwise around point 163. This is shown at

1       step 15B(i). Load-lock arm 160 pivots about pivot point 163  
2       90° counterclockwise as shown at step 15B(j), and then rotates  
3       90° about pivot point 167 as shown at 15B(k), so that the  
4       processed wafer now faces downward. Load-lock 20 is closed at  
5       this time, and processing of the wafer inserted into chamber 12  
6       at step 15B(i) has begun. Transfer arm 140 has, in the  
7       meantime, engaged a new unprocessed wafer as shown at step  
8       15B(k), and the unprocessed wafer is deposited upon the upper  
9       vacuum chuck of load-lock arm 160 as shown at 15B(l), returning  
10      the apparatus to the beginning of the cycle, which is the same  
11      as that shown in FIG. 15A(a).

12           Accordingly, load-lock arm 160 provides an efficient  
13       and versatile way of transferring wafers between transfer arm  
14       140 and load-lock 20. The rotation of arm 160 about axes 163  
15       and 167 and the provision of two vacuum chucks 162 allow one  
16       mechanism, in a minimum amount of time and space, to handle  
17       both processed and unprocessed wafers.

18           FIG. 17 is a top sectional view of the apparatus  
19       through section lines 17-17 of FIG. 2. As shown, a section is  
20       taken through both the load-lock station 20 and a sputtering  
21       station 22. Load-lock station 20 includes a front-plane device  
22       generally indicated at 27 and sputtering station 22 includes a  
23       back-plane device generally indicated at 47 and which is  
24       similar to front-plane device 27. Chamber 12 defined by  
25       chamber halves 14 and 16 includes index plate generally  
26       indicated at 15 which is shown in greater detail in FIG. 26.  
27       Index plate 15, as shown in FIG. 26, is driven by motor 18 and  
28       has four positions, each of which is provided with a substrate  
29       holding device as shown in greater detail in FIG. 24.

30           Before describing the operation of the apparatus with

reference to FIGS. 17 through 23, the substrate holding device of FIG. 24 will be described. The substrate holding device forms part of the sealing members A, B, C and D discussed with reference to FIG. 3A, the operation of which will be described in detail below. A portion of the index plate 15 is shown in FIG. 24. Index plate 24 includes four circular cutouts 200 (See FIG. 26), of which one is shown in FIG. 24. A plurality of tabs 202, illustratively three, are provided which extend into the cutout 200. A plurality of arc-shaped flat springs 208, illustratively three, are attached to respective ones of the tabs 202. At the end of the springs 208 farthest from tabs 202, an attachment is made to tabs 214 which extend from an outer ring-shaped sealing member 220. A further inner ring-shaped member 222 is disposed concentrically inside ring-shaped member 220. Ring-shaped member 222 is removably insertable into ring-shaped member 220, and includes a plurality of further spaced arcuate flat springs 224 attached to the ring-shaped member 222 via screws, for example, as shown at 230. At the other ends of springs 224, spring detent members 234, mounted in blocks 235, are disposed. The detent members engage with recesses 244 in outer ring-shaped member 220 and allow ring-shaped member 222 to be decoupled from ring-shaped member 220. Detent member 234 is made of an insulating material such as ceramic or a high temperature plastic material so that the ring 222 and substrate 72 can be insulated from the remainder of the apparatus. This allows the substrate 72 to be properly biased, for example, for sputtering and etching operations.

Outer ring-shaped member 220 can move perpendicularly to the plane of the index plate 15 with respect to index plate 15, and inner ring-shaped member 222 can move perpendicularly

1       with respect to outer ring-shaped member 220 due to the  
2       respective springs 208 and 224. The operation of springs 208  
3       and 224 will be explained in greater detail below. Ring 222  
4       has mounted on the backside thereof tabs 240, which tabs  
5       provide a backrest for a substrate 72 held by ring 222. Ring  
6       222 also includes a plurality of substrate securing devices  
7       238, which are engaged by rotatable locking and unlocking  
8       devices 166 which are mounted on load-lock arm 160.

9       As shown in further detail in FIGS. 20 and 21,  
10      securing devices 238 include a roughly channel-shaped member  
11      241 having a slot 241a and a central aperture therein for  
12      receiving a screw or other fastener 242. Attached to the  
13      channel-shaped member 241 is a retaining member 245, which can  
14      be rotated so that it extends into the area occupied by the  
15      peripheral edge of substrate 72 once it is positioned inside  
16      inner ring 222. Channel-shaped member 241 is fastened in a  
17      slot 247, the slot being provided for adjustment of the  
18      position of member 241. Channel-shaped member 241 is pivotably  
19      mounted on fastener 242. The channel 241a in channel-shape  
20      member 241 is engaged by a pair of longitudinally extending  
21      rods 168 extending from locking and unlocking device 166.

22      Locking and unlocking device 166 may comprise, for example, a  
23      small servo motor 170 or air or hydraulically actuated member.

24      As shown, locking and unlocking device 166 includes rod members  
25      168 at both ends thereof, since load-lock arm 160 is provided  
26      with two opposed vacuum chucks 162. As shown in FIGS. 20 and  
27      24, channel-shaped member 241 is disposed so that the slot 241a  
28      in the member is generally aligned tangentially with inner ring  
29      222 when substrate 72 is clamped in place. Accordingly, member  
30      245 is disposed so that it extends over the edge of the

substrate 72 and substrate 72 is firmly held between tabs 240 of ring 222 and members 245. When the load-lock arm 160 is to remove a substrate from the load-lock station 20, vacuum chuck 162 approaches the substrate 72. At the same time, unlocking device 166 approaches channel-shaped member 241 so that the rods 168 are in alignment with the slot 241a in channel-shaped member 241. As vacuum chuck 162 engages the substrate 72, the rods 168 of locking and unlocking device 166 engage with the slot 241a in channel-shaped member 241. Once vacuum chuck 162 has engaged wafer 72 and rods 168 are engaged in the slot 241a in channel member 241, servo mechanism 170 is actuated to rotate rods 168 90°, as shown in FIG. 21. In this way, member 245 slides in an arcuate path so that it is no longer disposed over the edge of substrate 72. In the illustrated embodiment, three securing members 238 are provided spaced equidistantly around ring member 222, and accordingly, three locking and unlocking members 166 are provided. Therefore, all three members 245 are rotated out of the way at the same time.

Accordingly, substrate 72 can be removed by vacuum chuck 162.

When a substrate 72 is being placed in chamber 12, locking and unlocking members 166 rotate members 245 in the opposite direction so as to secure the wafer to the ring-shaped member 222.

Vacuum chuck 162 is illustrative of the vacuum chucks generally used throughout the apparatus of the invention. Generally, vacuum chucks 162 are supplied via vacuum supply lines 260. The face of the vacuum chuck includes an annular depression 262 and at least one lead-in line 264 to depression 262 from a central aperture 266. As shown in FIG. 21, load-lock arm 160 is rotatably disposed on a shaft 268, so that

1 either one of the vacuum chucks 162 can enter the load-lock  
2 station 20 as discussed with respect to FIGS. 15A and B.

3 Preferably, vacuum check 162 comprises a first member  
4 162a which engages the substrate 72 and a second inner member  
5 162b. Members 162a and 162b are coupled via a flat spring  
6 member 162c which allows member 162a to move transversely to  
7 member 162b, thus allowing member 162a to conform to the plane  
8 of the substrate being engaged.

9 With reference now to FIGS. 17 and 18, FIG. 17 shows  
10 load-lock station 20 to the right with load-lock door 25  
11 closed. FIG 18 shows load-lock door 25 in the open position.  
12 FIGS. 17 and 18 show index plate 15 rotatably mounted in  
13 chamber 12 defined by chamber halves 14 and 16. As shown in  
14 FIGS. 17 and 18, front-plane device 27 at load-lock station 20  
15 may comprise a motor or hydraulically or air actuated member  
16 300 mounted to support 308. The shaft 302 of member 300 is  
17 mounted to a first sealing member 304. Sealing member 304  
18 preferably comprises a cup-shaped member and a bellows 306 may  
19 be provided to protect shaft 302 extending between support  
20 member 308 and cup-shaped member 304 and also to provide  
21 sealing. Cup-shaped member 304 includes a first sealing  
22 surface disposed annularly around the rim thereof, and may  
23 comprise, e.g., an O-ring seal 311. Seal 311 of member 304  
24 engages with a machined surface of outer ring-shaped member  
25 220. Both surfaces of outer ring-shaped member 220 are  
26 machined so as to provide a sealing surface, and the other  
27 surface of ring-shaped member 220 engages with a sealing  
28 surface of an annular extending portion 320 of chamber half 14.  
29 An O-ring seal 321 may be provided on portion 320. As will be  
30 explained in greater detail later, the O-ring seals 311 and 321

1 are provided for maintaining the environment in the load-lock  
2 station 20 area 330 or the chambers of each of the other  
3 processing stations 21, 22, or 23 isolated from main chamber  
4 volume 12a. Coupled to an inner portion of cup-shaped member  
5 304 is a support member 326 which is movable along with cup-  
6 shaped member 304 to provide support for substrate 72. Because  
7 substrate 72 is held firmly by ring-shaped member 222 which is  
8 attached to ring-shaped member 220 via flat springs 224,  
9 substrate 72 can move transversely to the plane in which it is  
10 disposed by a small amount without damage when member 326 moves  
11 toward substrate 72. Although member 326 may be arranged so  
12 that it contacts substrate 72, in the preferred embodiment,  
13 member 326 only comes into close proximity with substrate 72.  
14 At the load-lock station 20, front-plane member 326 is provided  
15 with heat sources for heating the entering substrate 72, shown  
16 in FIG. 18. This may be performed by suitable electric heaters  
17 390. Vacuum chucks 162 of load-lock arm 160 can then move in  
18 once load-lock door 25 has been opened, to engage or release a  
19 substrate and to lock or unlock securing members 238 and thus  
20 secure or release substrate 72.

21 With respect to FIGS. 1 and 2, load-lock door 25 is  
22 actuated by a suitable mechanism 19 via a shaft 19a pivotably  
23 mounted to the door 25 at 19b. Mechanism 19 may comprise,  
24 e.g., a motor driven gear rack or a suitable air or hydraulic  
25 cylinder.

26 As shown in FIGS. 17 and 18, the apparatus of the  
27 present invention isolates main chamber volume 12a from the  
28 area 330 defining the load-lock. Accordingly, once chamber 330  
29 has been isolated from main chamber 12, as shown in FIG. 18,  
30 the atmosphere in chamber 330 may be purged via a valve member

1 (not shown), and the pressure in chamber 330 equalized with  
2 that of the controlled environment 110 existing on the other -  
3 side of the load-lock door. Once the pressures have been  
4 equalized, the load-lock door can be opened, and vacuum chuck  
5 162 of load-lock arm 160 can enter the load-lock area 330 to  
6 pick up or release the substrate 72, depending upon whether a  
7 processed substrate is being removed or an unprocessed  
8 substrate inserted. This is shown in FIG. 18. As shown in  
9 FIG. 18, springs 208 which couple index plate 15 and outer ring  
10 220, allow ring-shaped member 220 and thus the inner ring 222  
11 and substrate 72 itself to move outwardly toward the load-lock  
12 door 25 so that the mentioned sealing of the area 330 defined  
13 by the cup-shaped member 304, ring-shaped member 220 and  
14 extending member 320 of chamber half 14 can be accomplished.

15 After a substrate 72 is inserted into area 330 of  
16 load-lock 20, load-lock door 25 is closed and the area 330  
17 pumped by a mechanical vacuum pump (not shown) and then by  
18 vacuum pump 40d. The vacuum level is equalized with the level  
19 in volume 12a and then front-plane cup-shaped member 304 moves  
20 away from ring-shaped member 220 to allow communication between  
21 volumes 12a and 330.

22 Similar sealing means are employed at each of the  
23 other stations 21, 22 and 23 to isolate the main chamber volume  
24 12a from the volume defining the particular station. In FIGS.  
25 17 and 18, like components have been provided with like  
26 reference symbols for station 20 and station 22, with the  
27 exception that the reference numerals for like already  
28 introduced elements of station 22 are provided with primes.  
29 For example, as shown in FIG. 17 or 18, which are top sectional  
30 views taken through the load-lock station 20 and the sputtering

0 244 951

station 22 (shown to the left), as shown by section lines 17 in FIG. 2, the volume 12a is isolated by the seal provided by members 304', 220' and the wall f chamber half 16 and associated seals 311' and 321'. Station 22 as shown in FIGS. 17 and 18, also includes a back-plane device 47, which is similar to front-plane device 27. Stations 21 and 23 include similar devices 37 and 57. Generally, element 326' is moved toward substrate 72 held by inner retaining ring 222' which is disposed in outer ring 220' via flat springs 224' and detents 234', the outer ring being fixed to index plate 15 via flat springs 208' and being engaged by sealing member 304'. Since station 22 may be a sputtering station, station 22 may include a removable cathode support member and cover 370 mounted to manifold 42, to which a target block 372 is affixed via a bolt 374, for example. Other suitable affixing means are shown in copending application Serial No. \_\_\_\_\_, assigned to the assignee of this application. Target block 372 comprises a usable, expendable material, for example, if aluminum is being deposited onto substrate 72, the target block 372 will comprise a block of aluminum. Designs for target 372 and the cathode area generally are disclosed more fully in copending application Serial Nos. \_\_\_\_\_ and \_\_\_\_\_, assigned to the assignee of this application, and reference is made thereto for details. As shown in FIG. 18, cathode support member 370 is attached to a door 431 and is hinged at 380 to a support structure 381 coupled to chamber half 16. O-ring seals 373 are provided for sealing manifold 42 to chamber half 16. Accordingly, access can be obtained to the interior of manifold 42 and to the cathode and target assembly, as necessary, without disturbing any other processing stations.

1            Suitable voltages are applied to target 372 with  
2            respect to chamber 12, and target 372 is suitably insulated  
3            therefrom by insulator 372a. Additionally, magnetic field  
4            generating means for appropriately containing the sputtered  
5            plasma in chamber 350 and for providing efficient and uniform  
6            deposition on substrate 72 may be provided in area 371 and also  
7            near the substrate itself, and reference is made to the above  
8            copending applications for details. Furthermore, as already  
9            indicated, the substrate 72 may be biased at some suitable  
10          voltage, and support ring 222 or 222' is insulated from the  
11          rest of the apparatus by insulating detents 234.

12          For process uniformity, for example, for uniform step  
13          coverage, an electromagnetic or magnet assembly 371a may be  
14          provided on the back-plane members of sputtering stations 22  
15          and 23, as shown. The purpose of assembly 371a is to provide  
16          substantially uniform ion current density near the substrate  
17          72. Reference should be made to the above identified co-  
18          pending application Serial No. \_\_\_\_\_ for details.

19          As shown in FIG. 18, back-plane device 47 operates to  
20          displace member 326' so that it engages substrate 72 mounted in  
21          support ring 222'. Since support ring 222' is resiliently  
22          mounted due to the flat springs 224' coupling it to outer ring  
23          member 220', which in turn is resiliently coupled by flat  
24          springs 208' to index plate 15, member 326' can come into close  
25          proximity with substrate 72 without damaging the substrate  
26          while at the same time allowing member 304' to bear against  
27          ring-shaped member 220', which in turn bears against chamber  
28          half 15, thereby sealing volume 350 from volume 12a. O-ring  
29          seals 311' and 321' are provided for maintaining a proper seal.  
30          Accordingly, the sputtering operation can now be performed

1 against substrate 72 in chamber volume 350 without  
2 contaminating the main volume 12a or contaminating any other -  
3 station 20, 21 or 23. Once the sputtering operation has been  
4 completed, the atmosphere in chamber volume 350 can be purged  
5 via vacuum pump 32 and manifold 42, and once the atmosphere in  
6 chamber 350 has been purged and the pressures equalized between  
7 chamber 350 and chamber volume 12a, back-plane members 304' and  
8 326' can be moved out of engagement or proximity with ring-  
9 shape member 220' and substrate 72, respectively, thereby  
10 allowing the index plate 15 to rotate the processed wafer 72 to  
11 the next station.

12 FIG. 19 is a more detailed cross-sectional view of  
13 station 22 of the present invention taken along lines 19-19 of  
14 FIG. 2. Cryogenic vacuum pump 32 and manifold 42 are shown at  
15 the bottom of the figure. Back-plane device 47, including  
16 actuator 390' is also shown. In this view, details of the  
17 cross-section of wafer holding rings 220' and 222' are shown.  
18 As shown, inner wafer retaining ring 222' includes hollow  
19 sections 223' in which springs 224' are disposed. As shown  
20 more clearly in FIG. 19, vacuum pump 32 maintains the proper  
21 vacuum level in chamber 350, which is isolated by sealing ring  
22 220' and the O-ring seals 311' and 321' when member 304' biases  
23 ring-shaped member 220' against chamber half 16. Back-plane  
24 member 326' is provided with electric heater devices 390 which  
25 are fed via wire conductors 392. Electric heaters 390 may be  
26 necessary in certain instances where it is desired to heat the  
27 substrate 72 to an optimum temperature for the particular  
28 process being carried out. Additionally, it may also be  
29 necessary to cool back-plane member 326' and member 304' to  
30 maintain the temperature of substrate 72 at a desired

1       temperature. Accordingly, cooling lines 394 and 395 may be  
2       provided for passing a cooling fluid through the back-plane -  
3       device. Also shown in FIG. 19 are shields 400 and 402, which  
4       are provided for shielding retaining ring 222', sealing ring  
5       220' and associated components from the plasma generated during  
6       the sputtering operation in space 350.

7       PIGS. 22 and 23 show further details of station 22.  
8       FIG. 22 shows back-plane member 326' prior to its coming into  
9       close proximity with substrate 72 held by inner ring 222'.  
10      FIG. 23 shows ring 220' after it has been engaged by back-plane  
11      member 304'. Back-plane member 326' is also shown in close  
12      proximity with substrate 72. Springs 208' allow sealing ring  
13      220' to move toward chamber wall 16. As shown in FIG. 23,  
14      springs 208' have been deflected by the force exerted by member  
15      304' against ring member 220'. O-ring seals 311' and 321' seal  
16      volume 12a from volume 350. Springs 224' allow for slight  
17      movement of ring member 222' and accordingly, substrate 72,  
18      with respect to ring 220', thus preventing damage to substrate  
19      72 when back-plane member 326' comes into close proximity  
20      therewith.

21       FIGS. 22 and 23 show further details of the cooling  
22      means provided at each of the sputtering stations. For  
23      example, fluid cooling lines 410 may be provided to cool the  
24      support structure in the area of the substrate 72. The various  
25      cooling lines are shown in FIG. 25 at 437. Additional cooling  
26      lines may be provided in the area of target 372 as shown at 412  
27      and 412a. Furthermore, the various fasteners, for example,  
28      screws 414 which fasten shield 402 to back-plane member 326',  
29      generally are provided either with heads with drilled vent  
30      holes or the member to which they are fastened is provided with

1       vents 416. Such vents or drilled heads are necessary in order  
2       that pockets of air not be trapped beneath the fasteners during  
3       assembly, which might otherwise later contaminate the evacuated  
4       volumes.

5                  As shown in the drawings, inner ring-shaped member  
6       222' remains in contact with substrate 72 during the  
7       performance of each process step, thus preventing particulate  
8       formation and breakage of substrate 72 which might otherwise  
9       occur if substrate 72 were transferred between different  
10      handling mechanisms.

11                 FIG. 25 is a right side view of the overall apparatus  
12      shown in FIG. 1. The overall layout of stations 20, 21, 22 and  
13      23 and the various pumps is shown therein. As shown in FIG.  
14      25, chamber half 16 is hinged to chamber half 14 at 425.  
15      Suitable locking devices are provided at 427 and shown in  
16      sectional view in FIGS. 17 and 18 to lock chamber halves 14 and  
17      16 together. Further hinges 380 allow each of the right side  
18      manifold doors of station sections 21, 22 and 23 mounted to  
19      chamber half 16 to be opened, for example, for replacement of  
20      targets at stations 22 and 23. A station door is shown at 431,  
21      for example, in FIG. 18 and FIG. 25. Suitable locking members  
22      429 can be provided for locking each of the right-side station  
23      doors in position. FIG. 18 shows station 22 door 431 holding  
24      cathode and target support member and cover 370 in the opened  
25      position in phantom view, for example. Member 370 may be  
26      secured to the station door by bolts or other suitable locking  
27      or fastener members.

28                 In the illustrated embodiment, station 21 is an  
29      etching station, and accordingly, a cathode and associated  
30      cover is not provided. Also, because station 20 is the load-

1 lock, as shown in FIG. 25, a door need be provided at that  
2 station.

3 In the foregoing specification, the invention has  
4 been described with reference to a specific exemplary  
5 embodiment thereof. It will, however, be evident that various  
6 modifications and changes may be made thereunto without  
7 departing from the broader spirit and scope of the invention as  
8 set forth in the appended claims. The specification and  
9 drawings are, accordingly, to be regarded in an illustrative  
10 rather than in a restrictive sense.  
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The invention thus provides:

Apparatus for transporting a wafer-like article and subjecting the article to at least one process step comprising:

means defining a first chamber maintained substantially continuously at a vacuum or pressure level;

aperture means in said first chamber through which an article to be subjected to the process step can be introduced into the first chamber;

means in said first chamber for receiving and holding the article;

means for moving the article held by said receiving and holding means substantially in a plane of movement to a position in the first chamber adjacent where the process step is to be performed on the article;

movable means for isolating the second chamber from communication with said first chamber while said process step is performed on the article and for thereafter opening said second chamber to the first chamber so that the second chamber is in communication with the first chamber after the article has been subjected to the process step, said receiving and holding means remaining in contact with the article during the performance of the process step; and

means for removing the article from said first chamber after the article has been subjected to the process step.

Such apparatus wherein said moving means comprises rotatable plate means disposed for movement in said plane of movement and said means for removing

0 244 951

the article comprises said aperture means through which the article is inserted into the first chamber.

Such apparatus wherein said receiving and holding means comprises:

first means coupled to said plate means and defining an inner open area;

first resilient means coupling said plate means and first means;

second means disposed in said inner open area and coupled to said first means, said second means defining a further area contained within said inner open area for receiving the article; and

second resilient means coupling said second means to said first means.

Such apparatus wherein said first means comprises sealing surfaces on first and second surfaces thereof, and said movable means comprises:

closure means movable toward and away from one of the first and second surfaces and having a surface for engaging in sealing relationship with said one of said first and second surfaces of said first means;

said means defining the first chamber having a further surface for engaging in sealing relationship with the other of the first and second surfaces of said first means;

said first resilient means allowing said closure means to bias said otherof said first and second surfaces of the first means against the further surface of said means defining the first chamber in a direction substantially

perpendicular to the plane of said plate means,

whereby, when said closure means engages said one of said first and second surfaces and said other of said first and second surfaces engages the further surface, said second chamber is sealed from said first chamber.

Such apparatus wherein said first and second resilient means each comprise flat spring means.

Such apparatus wherein said article comprises a circular wafer and said first means comprises first ring-shaped member means, said second means comprises second ring-shaped member means and said first and second resilient means comprise arcuate flat spring means.

Such apparatus wherein said closure means comprises cup-shaped means with said surface of said closure means for engaging in sealing relationship comprising a rim of said cup-shaped means.

Such apparatus wherein said second means is removably coupled to said first means by electrically insulating detent means.

Such apparatus wherein said first and second means are disposed concentrically and said first resilient means is disposed between said plate means and said first means and said second resilient means is disposed between said second means and said first means.

Such apparatus

further

comprising backing means coupled to said closure means and disposed in an area defined by the interior of said closure means for coming into close proximity with a surface of the article held in said second means when said closure means moves toward said one of said first and second surfaces.

Such apparatus

wherein said

second resilient means comprises means for allowing the article to move substantially perpendicularly to a plane defined by said first means when said backing means comes into close proximity with said article.

Such apparatus

wherein said

second ring-shaped member means includes an edge along at least a part of an inner periphery thereof extending into the further area against which peripheral portions of the article can be received, and further comprising clamping means disposed on said second means for clamping the article to the second means and movable so that a portion thereof can be moved into a position extending over at least a part of the further area defined by the inside of the second means.

Such apparatus

wherein said

clamping means is rotatably movable over at least a part of the further area defined by the inside of the second means.

Such apparatus

further

comprising door means disposed in said aperture means for sealing said first chamber from the external environment.

Such apparatus

- further

comprising a further second chamber defined by said aperture means and said door means, and further comprising further movable means disposed behind said door means for isolating said further second chamber from communication with said first chamber while said article is being introduced into or removed through said aperture means.

Such apparatus

wherein said

rotatable plate means comprises disk means rotatably movable in said first chamber about a central axis, said disk means comprising means for holding a plurality of said receiving and holding means, and said means defining said first chamber comprises means for supporting a plurality of second chambers defining work stations at positions spaced approximately equi-angularly and equi-distantly about said central axis, movable means being provided adjacent each of said second chambers with said disk means being disposed between said movable means and a respective second chamber such that said receiving and holding means are rotated into a position between said respective second chamber and said movable means, said movable means being provided for isolating the respective second chamber from communication with the first chamber while the process step is performed on the article in the second chamber and for thereafter opening the second chamber to the first chamber so that the second chamber is in communication with the first chamber after the article has been subjected to the process step, the process step performed in each of said second chambers thereby being isolated from the process step performed in any other second chamber.

Such apparatus wherein said plate means comprises a plurality of locations equi-angularly spaced about a central axis of the plate means for supporting respective ones of said receiving and holding means, each of said receiving and holding means comprising:

" first means coupled to said plate means and defining an inner open area;

" first resilient means coupling said plate means and first means;

" second means disposed in said inner open area and coupled to said first means, said second means defining a further area contained within said inner open area for receiving the article; and

second resilient means coupling said second means to said first means, said first means further comprising sealing surfaces on first and second surfaces thereof, each of said movable means comprising:

closure means movable toward and away from one of the first and second surfaces and having a surface for engaging in sealing relationship with said one of said first and second surfaces of said first means;

said means defining the first chamber having a further surface for engaging in sealing relationship with the other of the first and second surfaces of said first means;

said first resilient means allowing said closure means to bias said other of said first and second surfaces of the first means against the further surface of said means defining the first chamber in a direction substantially perpendicular to the plane of said plate means,

whereby, when said closure means engages said

**0 244 951**

one of said first and second surfaces and said other of said first and second surfaces engages the further surface, said respective second chamber is sealed from said first chamber.

Such apparatus further comprising pump means associated with each of said second chambers for providing an atmosphere at a defined pressure or vacuum level in the respective second chamber and further comprising gas inlet means for providing a gas into the respective second chamber for the process step.

Such apparatus wherein said work stations comprise a load-lock station including said aperture means whereby the article can be inserted into or removed from the first chamber, a station wherein the article can be subjected to an etching process and at least one station wherein the article can be subjected to a sputter deposition process.

Such apparatus wherein each of said stations comprises door means for allowing individual access to the respective second chamber, and said means defining a first chamber comprises first and second chamber portions engaging in sealing relationship along an approximate center line of the first chamber, thereby allowing said first and second chamber portions to be removably uncoupled to each other to allow access to the interior of said first chamber.

Such apparatus further comprising article handling means for receiving an article to

be subjected to the process step from a carrier member having disposed therein a plurality of said articles and for supplying an article that has been subjected to the process step to the carrier member.

Such apparatus wherein said article handling means comprises:  
means for retrieving an article from said carrier member and for placing said article on a movable support member;  
first arm means for receiving the article from the movable support member; and  
second arm means for receiving said article from said first arm means and for inserting said article into said aperture means in said first chamber.

Such apparatus wherein said first and second arm means are disposed in a third chamber isolated from said first chamber and the external environment.

Such apparatus whereas said first arm means comprises means movable in a first plane and said second arm means comprises means movable in said first plane or in a plane parallel to said first plane.  
Such apparatus wherein said third chamber includes entry means for receiving an article from said movable support means, and said movable support means comprises means for engaging in sealing relationship with a sealing surface arranged around said entry means when an

article is inserted thru said entry means.

Such apparatus wherein said entry means comprises movable sealing means disposed in said third chamber for forming a fourth chamber in said third chamber about the article isolated from said third chamber.

Such apparatus further comprising valve means for purging the atmosphere in said fourth chamber and for supplying an atmosphere into said fourth chamber having a pressure approximately the same as the pressure in said third chamber.

Such apparatus wherein the atmosphere in said third chamber comprises a substantially inert water-free atmosphere.

Such apparatus wherein said first arm means is movable in an arcuate path and said movable sealing means is movable so as to open said third chamber to said fourth chamber when the pressures in said third and fourth chambers have substantially equalized, thereby allowing access by said first arm means to said article.

Such apparatus wherein said second arm means comprises means pivotable in said first plane or a plane parallel to said first plane so that an end of said second arm means defines an arcuate path for receiving the article from said first arm means at a defined position along said path and further being rotatable about a longitudinal

extent of said second arm means.

Such apparatus wherein said second arm means comprises first and second engaging means disposed on the end of the second arm means, one of said engaging means adapted for receiving an article from said first arm means in the first plane or a plane parallel to the first plane and the other adapted for transferring an article to said first arm means in said first plane or a plane parallel to said first plane, said second arm means being adapted for rotating the article engaged by either of said engaging means about the longitudinal extent of the second arm means so that the article can be inserted into said aperture means in said first chamber by the second arm means or received through said aperture means in said first chamber by said second arm means for transfer to said first arm means.

Such apparatus wherein said first arm means comprises vacuum chuck means, said first and second engaging means of said second arm means comprise vacuum chuck means and further comprising locking and unlocking means for engaging with said clamping means disposed on said second arm means.

The invention thus provides

apparatus for transporting a wafer-like article and subjecting the article to at least one process step comprising:

means defining a first chamber maintained substantially continuously at a vacuum or pressure level; aperture means in said first chamber through



which an article to be subjected to the process step can be introduced into the first chamber;

means in said first chamber for receiving and holding the article;

a plurality of second chambers in any of which a process step can be performed on the article;

means for moving the article held by said receiving and holding means substantially in a plane of movement to a position in the first chamber adjacent a selected one of said second chambers where the process step is to be performed;

movable means for isolating the selected second chamber from communication with the first chamber while said process step is performed on the article and for thereafter opening said second chamber to the first chamber so that the second chamber is in communication with the first chamber after the article has been subjected to the process step, said receiving and holding means remaining in contact with the article during the performance of the process step; and

means for removing the article from the first chamber after the article has been subjected to the process step.

Such apparatus wherein said moving means comprises rotatable plate means disposed for movement in said plane, said moving means comprises a plurality of means for receiving and holding articles and said means for removing the article comprises said aperture means through which the article is inserted into the first chamber.

Such apparatus wherein said moving means comprises means for moving the article held by said receiving and holding means to a position in the first chamber adjacent the selected one of said second chambers where the process step is to be performed and for moving the article held by said receiving and holding means to a further selected one of said second chambers where a further process step may be performed on the article.

Such apparatus wherein said receiving and holding means comprises:

first means coupled to said plate means and defining an inner open area;

first resilient means coupling said plate means and first means;

second means disposed in said inner open area and coupled to said first means, said second means defining a further area contained within said inner open area for receiving the article; and

second resilient means coupling said second means to said first means.

Such apparatus wherein said first means comprises sealing surfaces on first and second surfaces thereof, and said movable means comprises:

closure means movable toward and away from one of the first and second surfaces and having a surface for engaging in sealing relationship with said one of said first and second surfaces of said first means;

said means defining the first chamber having a

0 244 951

further surface for engaging in sealing relationship with the other of the first and second surfaces of said first means;

said first resilient means allowing said closure means to bias said other of said first and second surfaces of the first means against the further surface of said means defining the first chamber in a direction substantially perpendicular to the plane of said plate means,

whereby, when said closure means engages said one of said first and second surfaces and said other of said first and second surfaces engages the further surface, said second chamber is sealed from said first chamber.

Such apparatus wherein said first and second resilient means each comprise flat spring means.

Such apparatus wherein said article comprises a circular wafer and said first means comprises first ring-shaped member means, said second means comprises second ring-shaped member means and said first and second resilient means comprise accurate flat spring means.

Such apparatus wherein said closure means comprises cup-shaped means with said surface of said closure means for engaging in sealing relationship with said one surface of first means comprising a rim of said cup-shaped means.

Such apparatus wherein said second means is removably coupled to said first means by



electrically insulating detent means.

Such apparatus wherein said first and second means are disposed concentrically and said first resilient means is disposed between said plate means and said first means and said second resilient means is disposed between said second means and said first means.

Such apparatus further comprising backing means coupled to said closure means and disposed in an area defined by the interior of said closure means for coming into close proximity with a surface of the article held in said second means when said closure means moves toward said one of said first and second surfaces.

Such apparatus wherein said second resilient means comprises means for allowing the article to move substantially perpendicularly to a plane defined by said first means when said backing means comes into close proximity with said article.

Such apparatus wherein said second ring-shaped member means includes an edge along at least a part of an inner periphery thereof extending into the further area against which peripheral portions of the article can be received, and further comprising means for clamping the article to said second means, said claiming means comprising means disposed on said second means movable so that a portion thereof can be moved into a position extending over at least a part of the further area defined by the inside of the second means.

0 244 951

Such apparatus wherein said clamping means is rotatably movable over at least a part of the further area defined by the inside of the second means.

Such apparatus further comprising door means disposed in said aperture means for sealing said first chamber from the external environment.

Such apparatus further comprising a further second chamber defined by said aperture means and said door means between said door means and said first chamber, and further comprising further movable means disposed behind said door means for isolating said further second chamber from communication with said first chamber while said article is being introduced into or removed through said aperture means.

Such apparatus wherein said rotatable plate means comprises disk means rotatably movable in said first chamber about a central axis, said disk means comprising means for holding a plurality of said receiving and holding means, and said means defining said first chamber comprises means for supporting a plurality of second chambers defining work stations at positions spaced approximately equi-angularly and equi-distantly about said central axis, movable means being provided adjacent each of said second chambers for isolating the respective second chamber from communication with the first chamber while the process step is performed on the article in the second chamber and for thereafter opening the second chamber to the first chamber so that the second chamber

0 244 951

is in communication with the first chamber after the article has been subjected to the process step, the process step performed in each of said second chambers thereby being isolated from the process step performed in any other second chamber.

Such apparatus further comprising pump means associated with each of said second chambers for providing an atmosphere at a defined pressure or vacuum level in the respective second chamber and further comprising gas inlet means for each second chamber for providing a gas into said second chamber for said process step.

Such apparatus wherein said work stations comprise a load-lock station whereby the article can be inserted into or removed from the first chamber, a station wherein the article can be subjected to an etching process and at least one station wherein the article can be subjected to a sputter deposition process.

Such apparatus wherein each of said stations comprises door means for allowing individual access to the respective second chambers.

Such apparatus wherein said means defining a first chamber comprises first and second chamber portions engaging in sealing relationship along an approximate center line of the first chamber, thereby allowing said first and second chamber portions to be removably uncoupled to each other to allow access to the interior of said

first chamber.

Such apparatus further comprising article handling means for receiving an article to be subjected to the process step from a carrier member having disposed therein a plurality of said articles and for supplying an article that has been subjected to the process step to the carrier member.

The invention thus provides apparatus for holding a wafer-like article in a movable support means and for allowing movement transverse to said support means comprising:

first means coupled to the support means and defining a first inner open area;

first resilient means coupling said support means and first means;

second means disposed in said inner open area and coupled to said first means, said second means defining a second inner open area contained within said first area for receiving the article;

second resilient means coupling said second means to said first means; and

means disposed on said second means for securing the article disposed in said second area to said second means.

Such apparatus further comprising a first chamber in which the apparatus is disposed and a second chamber in communication with the first chamber and wherein said first means comprises sealing surfaces on first and second surfaces thereof, one of said first and second

surfaces being engageable in sealing relationship with a surface of wall means of the first chamber in which the apparatus is disposed and the other surface being engageable in sealing relationship with movable closure means for isolating the second chamber from the first chamber while a process step is performed on the article in the second chamber, said closure means comprising means movable toward and away from the article and having a further surface for engaging in sealing relationship with the other surface of the first means, said first resilient means allowing said closure means to bias the one of said first and second surfaces of said first means against said surface of said wall means in a direction substantially perpendicular to the plane of said wall means when said closure means moves toward and engages said other surface of said first means, said second chamber being isolated from said first chamber when said further surface of said closure means engages said other surface of said first means and said one surface of said first means engages with said surface of said wall means.

Such apparatus wherein said wafer-like article is circular in shape and said first means comprises first ring-shaped member means and said second means comprises second ring-shaped member means.

Such apparatus wherein said first and second resilient means each comprise flat, arcuate spring means.

Such apparatus wherein said

0 244 951

closure means comprises cup-shaped means, said further surface of said closure means comprising a rim of said cup-shaped means.

Such apparatus wherein said second means is removably coupled to said first means by detent means.

Such apparatus wherein said first and second ring-shaped means are disposed concentrically, and said first resilient means is disposed between said movable support means and said first means and said second resilient means is disposed between said second means and said first means.

Such apparatus further comprising backing means coupled to said closure means and disposed in an area defined by the inside of said closure means for coming into close proximity with a surface of the article held by said second means when said closure means moves toward said one of said first and second surfaces.

Such apparatus wherein said second resilient means comprises means for allowing the article to move substantially perpendicularly to a plane in which said first means is disposed when said backing means comes into close proximity with said article.

Such apparatus wherein said second ring-shaped means includes an edge along at least a part



of an inner periphery thereof extending into the area defined by the inside of said ring-shaped means against which peripheral portions of the article can be received, and said securing means comprises means disposed on said second means movable so that a portion thereof can be moved into a position over the area defined by the inside of the second ring-shaped means.

Such apparatus wherein at least a part of said securing means is rotatably movable over the area defined by the inside of the second ring-shaped means.

The invention thus provides method for transporting a wafer-like article and subjecting the article to at least one process step comprising the steps of:

introducing the article to be processed through aperture means into a first chamber maintained substantially continuously at a vacuum or pressure level;

receiving and holding the article in receiving and holding means in the first chamber;

moving the article held by said receiving and holding means to a position in the first chamber adjacent a second chamber where the process step is to be performed;

isolating the second chamber from communication with said first chamber while said process step is performed on the article and thereafter opening said second chamber to the first chamber so that the second chamber is in communication with the first chamber after the article has been subjected to the process step, said receiving and holding means remaining in contact with the article during the performance of the process

0 244 951

step, said receiving and holding means remaining in contact with the article during the performance of the process step; and

removing the article from the first chamber after the article has been subjected to the process step.

Such method wherein said step of receiving and holding comprises clamping the article to said receiving and holding means coupled to support means, said step of moving comprises rotating said support means disposed in the first chamber about a central axis and said step of removing the article comprises removing the article through the aperture means through which the article is inserted into the first chamber.

Such method wherein said step of clamping comprises receiving the article in the interior area of an inner one of two concentric ring means, the outer of the ring means being coupled to the support means by first resilient means and the inner ring means being coupled to the outer ring means by second resilient means.

Such method wherein said outer one of said ring means comprises sealing surfaces on first and second surfaces thereof, and further comprising the steps of:

moving closure means toward and away from one of the first and second surfaces and engaging a surface of the closure means in sealing relationship with said one of said first and second surfaces;

0 244 951

engaging a further surface of the first chamber  
in sealing relationship with the other of the first and second  
surfaces;

said first resilient means allowing said closure  
means to bias said other of said first and second surfaces  
against the further surface of said first chamber in a  
direction substantially perpendicular to the plane of said  
support means, whereby, when said closure means engages said  
one of said first and second surfaces and said other of said  
first and second surfaces engages the further surface, said  
second chamber is sealed from said first chamber.

Such . method further  
comprising the step of moving a support surface into close  
proximity to a surface of the article held by said inner ring  
means during said step of moving said closure means.

Such . method wherein said  
step of moving a support surface into close proximity to a  
surface of the article held in said inner ring means further  
comprises flexing said second resilient means thereby allowing  
the article to move substantially perpendicularly to a plane  
defined by said outer ring means.

Such method wherein said  
ring means includes an edge along at least a part of an  
inner periphery thereof extending into the interior area  
thereof against which peripheral portions of the article can be  
received, and said step of clamping comprises moving clamping  
means so that a portion thereof can be moved into a position

0 244 951

extending over at least a part of the area defined by the inside of the inner ring means.

Such method wherein said step of clamping comprises rotating said clamping means over at least a part of the area defined by the inside of the inner ring means.

Such method wherein said step of moving comprises rotating said article held in said support means in said first chamber to a position adjacent a selected one of a plurality of second chambers located at positions spaced approximately equi-angularly and equidistantly about a central axis of said support means and isolating the selected second chamber from the first chamber while the process step is performed on the article in the second chamber and thereafter opening the second chamber to the first chamber so that the second chamber is in communication with the first chamber after the article has been subjected to the process step, the process step performed in each of said second chambers thereby being isolated from the process steps performed in any of the second chambers.

Such method wherein said step of isolating comprises moving closure means associated with the respective second chamber toward the article held in said support means to thereby seal said second chamber from the first chamber.

Such method further

0 244 951

comprising the steps of receiving an article to be subjected to the process step from a carrier member having disposed therein a plurality of said articles and supplying an article that has been subjected to the process step to the carrier member.

Such method wherein said

step of receiving comprises:

retrieving an article from said carrier member

and placing said article on a movable support member;

moving said movable support member to a first intermediate position;

receiving the article in first arm means movable in a first plane from the movable support member at the first intermediate position; and

moving said first arm means in said first plane and transferring said article to second arm means at a second intermediate position and moving said second arm means so as to insert said article into said aperture means in said first chamber.

Such method wherein said

steps of receiving and transferring are performed in a third chamber isolated from said first chamber and the external environment.

Such method whereas said

step of moving said first arm means comprises moving said first arm means in a first plane and said steps of receiving said article from said first arm means and moving said second arm means so as to insert said article into said aperture means

**0 244 951**

comprises moving said second arm means in said first plane or in a plane parallel to said first plane and rotating said article about the longitudinal extent of said second arm means.

Such method wherein said third chamber includes entry means for receiving an article, and further comprising the step of engaging said movable support means in sealing relationship with a sealing surface arranged around said entry means when an article is inserted through said entry means by said movable support means.

Such method wherein said step of engaging comprises forming a fourth chamber in said third chamber about said article isolated from said third chamber.

Such method further comprising the steps of purging the atmosphere in said fourth chamber and supplying an atmosphere into said fourth chamber having a pressure approximately the same as the pressure in said third chamber.

Such method wherein said step of moving said first arm means comprises moving an end of said first arm means in an accurate path and said step of receiving the article in first arm means comprises the step of opening said third chamber to said fourth chamber when the pressures in said third and fourth chambers have substantially equalized, thereby allowing access by said first arm means to said article.

Such method

further

comprising the step of moving an end of said second arm means pivotably in said first plane or a plane parallel to said first plane in an arcuate path and receiving the article from said first arm means at said second intermediate position along said path and rotating the article about a longitudinal extent of said second arm means.

Such method

wherein said

step of moving said second arm means comprises receiving an article from said first arm means while another of said articles is held by said second arm means and thereafter transferring the other article to said first arms means in said first plane or a plane parallel to said first plane by rotating the article about the longitudinal extent of the second arm means so that the article can be received by said first arm means.

Such method

, further

comprising the steps of receiving an article in said second arm means from said first chamber while another of said articles is held by said second arm means and thereafter transferring the other article to said first chamber by rotating the article about the longitudinal extent of the second arm means so that the article can be inserted through said aperture means into said first chamber.

The invention thus provides a  
method for transporting a wafer-like article  
and subjecting the article to at least one process step  
comprising the steps of:

0 244 951

introducing the article to be processed through aperture means into a first chamber maintained substantially continuously at a vacuum or pressure level;

receiving and holding the article in receiving and holding means in the first chamber;

moving the article held by said receiving and holding means to a position in the first chamber adjacent a selected one of second chambers where the process step is to be performed;

isolating the selected second chamber from communication with the first chamber while said process step is performed on the article and thereafter opening said second chamber to the first chamber so that the second chamber is in communication with the first chamber after the article has been subjected to the process step, said receiving and holding means remaining in contact with the article during the performance of the process step; and

removing the article from the first chamber after the article has been subjected to the process step.

Such method wherein said step of moving comprises rotating support means disposed in the first chamber about a central axis and in which the receiving and holding means is disposed and said step of removing the article comprises removing the article through said aperture means through which the article is inserted into the first chamber.

Such method wherein said step of moving comprises moving the article held by said

0 244 951

receiving and holding means to a position in the first chamber adjacent the selected one of said second chambers where the process step is to be performed and further comprising the step of moving the article held by said receiving and holding means to a further selected one of said second chambers where a further process step may be performed on the article.

Such method wherein said step of receiving and holding comprises receiving the article in the interior area of an inner one of two concentric ring means, the outer of the ring means being coupled to the support means by first resilient means and the inner ring means being coupled to the outer ring means by second resilient means.

Such method wherein said outer one of said ring means comprises sealing surfaces on first and second surfaces thereof, and further comprising the steps of:

moving closure means toward and away from one of the first and second surfaces and engaging a surface of the closure means in sealing relationship with said one of said first and second surfaces;

engaging a further surface of the first chamber in sealing relationship with the other of the first and second surfaces;

said first resilient means allowing said closure means to bias said other of said first and second surfaces against the further surface of said first chamber in a direction substantially perpendicular to the plane of said support means, whereby when said closure means engages said one

of said first and second surfaces and said other of said first and second surfaces engages the further surface, said second chamber is sealed from said first chamber.

Such method further  
comprising the step of moving a support surface into close proximity to a surface of the article held by said inner ring means during said step of moving said closure means.

Such method wherein said step of moving a support surface into close proximity to a surface of the article held in said inner ring means further comprises flexing said second resilient means thereby allowing the article to move substantially perpendicularly to a plane defined by said outer ring means.

Such method wherein said inner ring means includes an edge along at least a part of an inner periphery thereof extending into the interior area thereof against which peripheral portions of the article can be received, and further comprising the step of moving clamping means so that a portion thereof can be moved into a position extending over at least a part of the area defined by the inside of the inner ring means.

Such method wherein said step of clamping comprises rotating at least a portion of said clamping means over at least a part of the area defined by the inside of the inner ring means.

Such method wherein said step of moving comprises rotating said article held in said support means in said first chamber to a position adjacent a selected one of a plurality of second chambers located at positions spaced approximately equi-angularly and equidistantly about a central axis of said support means and isolating the selected second chamber from the first chamber while the process step is performed on the article in the second chamber and thereafter opening the second chamber to the first chamber so that the second chamber is in communication with the first chamber after the article has been subjected to the process step, the process step performed in each of said second chambers thereby being isolated from the process step performed in any of the other second chambers.

Such method wherein said step of isolating comprises moving closure means associated with the respective second chamber toward the article held in said support means to thereby seal said second chamber from the first chamber.

Such method further comprising the steps of receiving an article to be subjected to the process step from a carrier member having disposed therein a plurality of said articles and supplying an article that has been subjected to the process step to the carrier member.

WHAT IS CLAIMED IS:

1. Apparatus for transporting a wafer-like article and subjecting the article to at least one process step comprising:

means defining a first chamber maintained substantially continuously at a vacuum or pressure level;

aperture means in said first chamber through which an article to be subjected to the process step can be introduced into the first chamber;

means in said first chamber for receiving and holding the article;

means for moving the article held by said receiving and holding means substantially in a plane of movement to a position in the first chamber adjacent where the process step is to be performed on the article;

movable means for isolating the second chamber from communication with said first chamber while said process step is performed on the article and for thereafter opening said second chamber to the first chamber so that the second chamber is in communication with the first chamber after the article has been subjected to the process step, said receiving and holding means remaining in contact with the article during the performance of the process step; and

means for removing the article from said first chamber after the article has been subjected to the process step.

2. The apparatus recited in claim 1, wherein said moving means comprises rotatable plate means disposed for movement in said plane of movement and said means for removing

0 244 951

3. Apparatus for transporting a wafer-like article and subjecting the article to at least one process step comprising:

means defining a first chamber maintained substantially continuously at a vacuum or pressure level; aperture means in said first chamber through

which an article to be subjected to the process step can be introduced into the first chamber;

means in said first chamber for receiving and holding the article;

a plurality of second chambers in any of which a process step can be performed on the article;

means for moving the article held by said receiving and holding means substantially in a plane of movement to a position in the first chamber adjacent a selected one of said second chambers where the process step is to be performed;

movable means for isolating the selected second chamber from communication with the first chamber while said process step is performed on the article and for thereafter opening said second chamber to the first chamber so that the second chamber is in communication with the first chamber after the article has been subjected to the process step, said receiving and holding means remaining in contact with the article during the performance of the process step; and

means for removing the article from the first chamber after the article has been subjected to the process step.

4. The apparatus recited in claim 3, wherein said moving means comprises rotatable plate means disposed for movement in said plane, said moving means comprises a plurality of means for receiving and holding articles and said means for removing the article comprising said aperture means through which the article is inserted into the first chamber.

5. Apparatus for holding a wafer-like article in a movable support means and for allowing movement transverse to said support means comprising:

first means coupled to the support means and defining a first inner open area;

first resilient means coupling said support means and first means;

second means disposed in said inner open area and coupled to said first means, said second means defining a second inner open area contained within said first area for receiving the article;

second resilient means coupling said second means to said first means; and

means disposed on said second means for securing the article disposed in said second area to said second means.

6. The apparatus recited in claim 5, further comprising a first chamber in which the apparatus is disposed and a second chamber in communication with the first chamber and wherein said first means comprises sealing surfaces on first and second surfaces thereof, one of said first and second

7. A method for transporting a wafer-like article and subjecting the article to at least one process step comprising the steps of:

introducing the article to be processed through aperture means into a first chamber maintained substantially continuously at a vacuum or pressure level;

receiving and holding the article in receiving and holding means in the first chamber;

moving the article held by said receiving and holding means to a position in the first chamber adjacent a second chamber where the process step is to be performed;

isolating the second chamber from communication with said first chamber while said process step is performed on the article and thereafter opening said second chamber to the first chamber so that the second chamber is in communication with the first chamber after the article has been subjected to the process step, said receiving and holding means remaining in contact with the article during the performance of the process step, said receiving and holding means remaining in contact with the article during the performance of the process step; and

removing the article from the first chamber after the article has been subjected to the process step.

8. The method recited in claim 7, wherein said step of receiving and holding comprises clamping the article to said receiving and holding means coupled to support means, said step of moving comprises rotating said support means disposed in the first chamber about a central axis and said step of removing the article comprises removing the article through the aperture means through which the article is inserted into the first chamber.

9. A method for transporting a wafer-like article and subjecting the article to at least one process step comprising the steps of:

introducing the article to be processed through aperture means into a first chamber maintained substantially continuously at a vacuum or pressure level;

receiving and holding the article in receiving and holding means in the first chamber;

moving the article held by said receiving and holding means to a position in the first chamber adjacent a selected one of second chambers where the process step is to be performed;

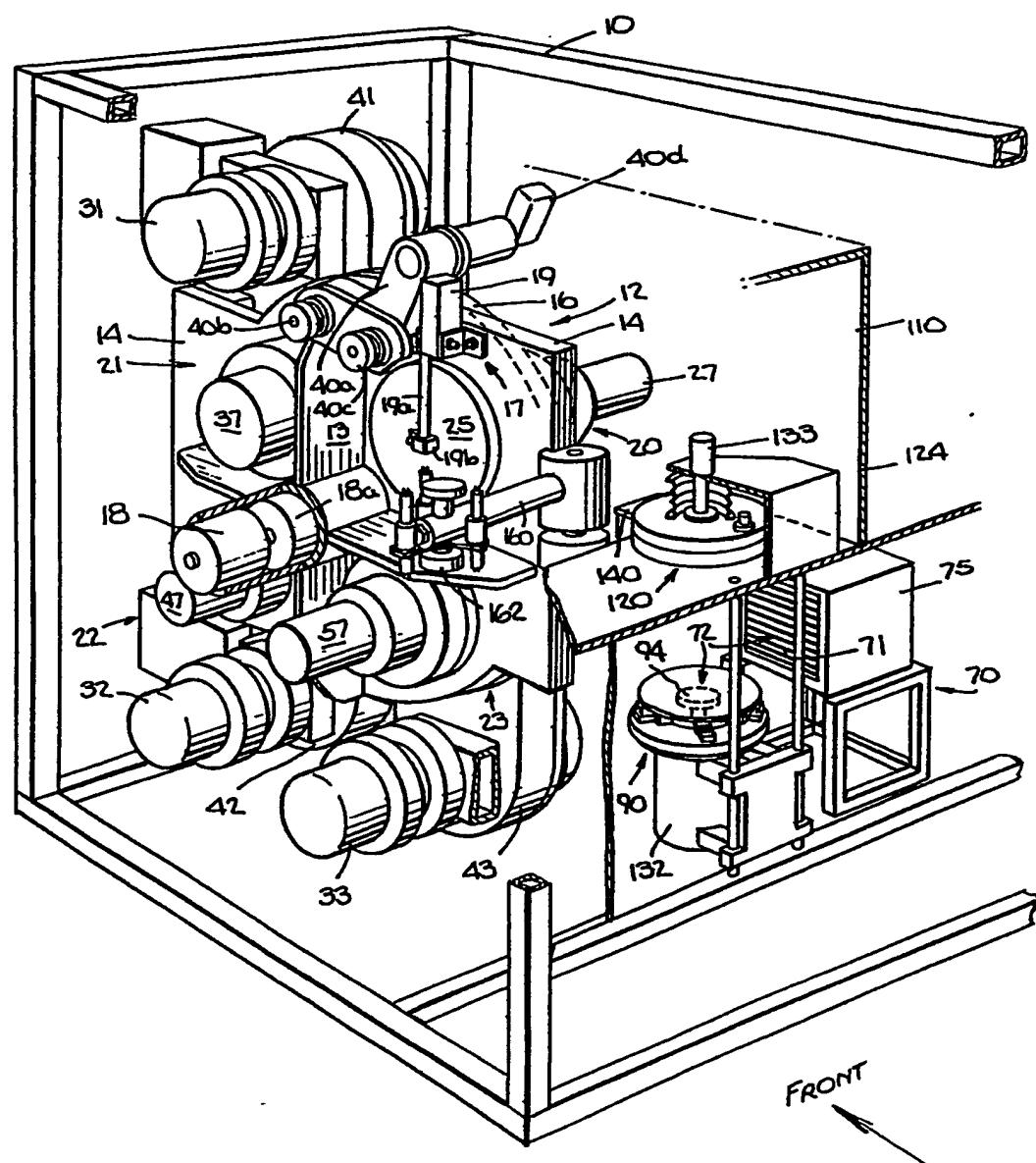
isolating the selected second chamber from communication with the first chamber while said process step is performed on the article and thereafter opening said second chamber to the first chamber so that the second chamber is in communication with the first chamber after the article has been subjected to the process step, said receiving and holding means remaining in contact with the article during the performance of the process step; and

removing the article from the first chamber after the article has been subjected to the process step.

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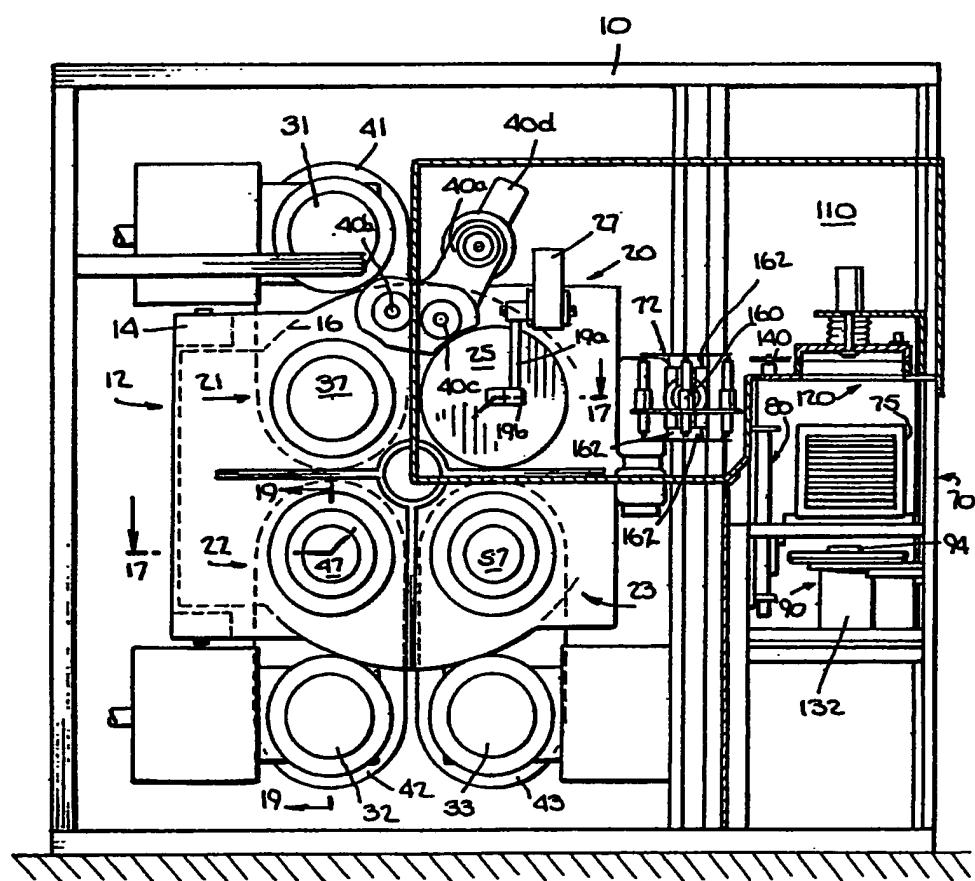
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Fig. 1.



2/26

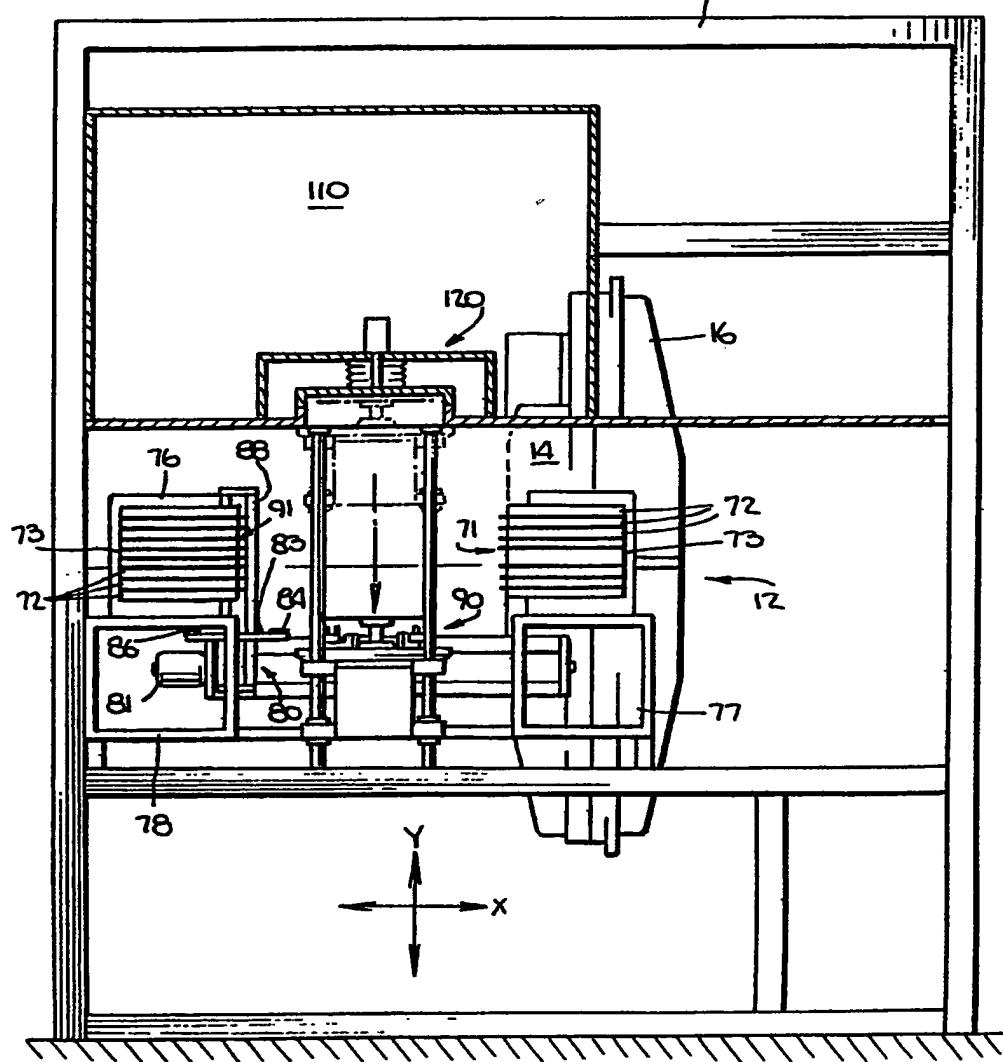
Fig. 2.

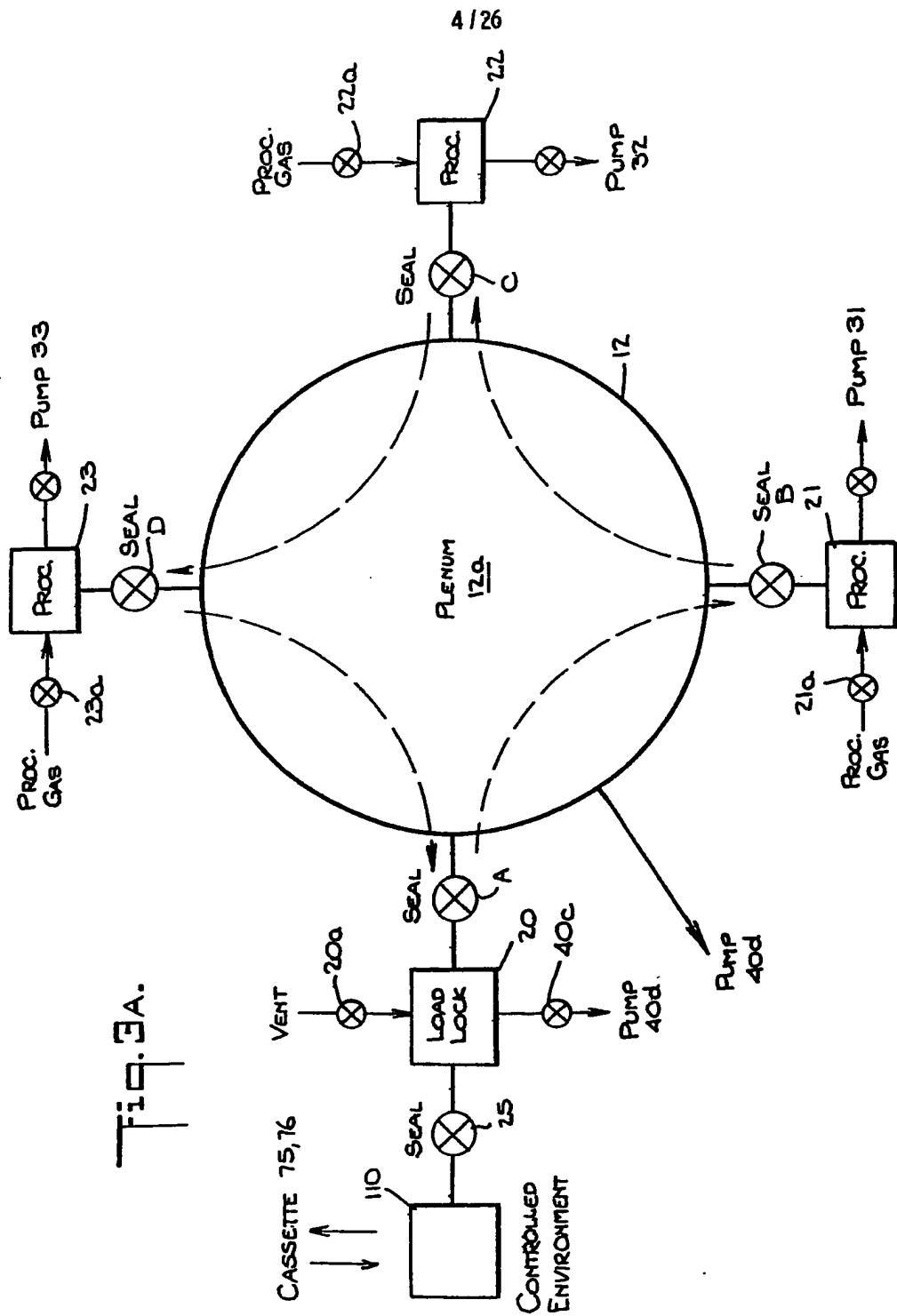


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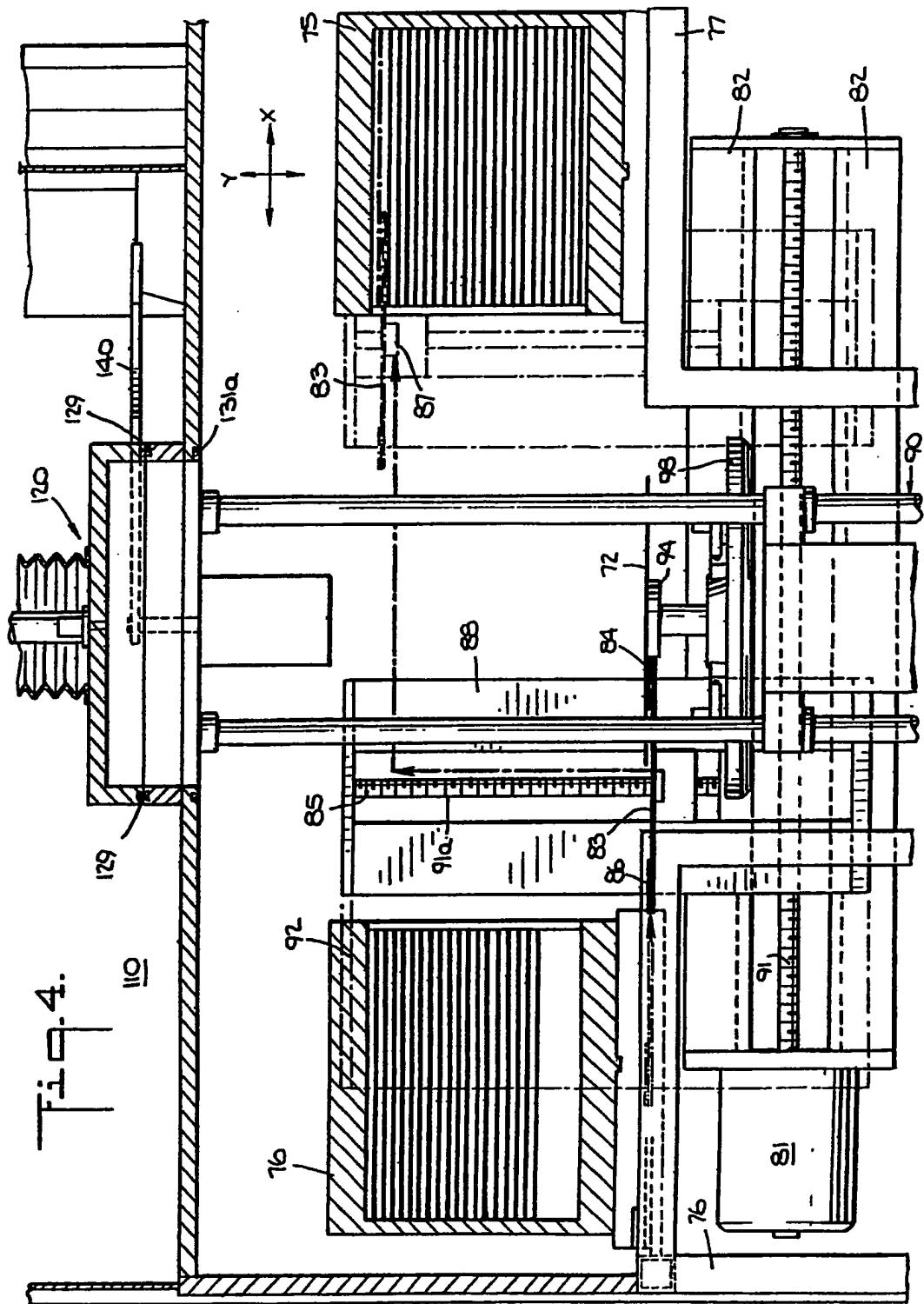
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Fig. 3.

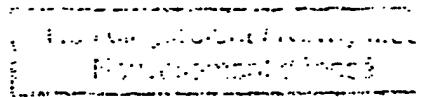




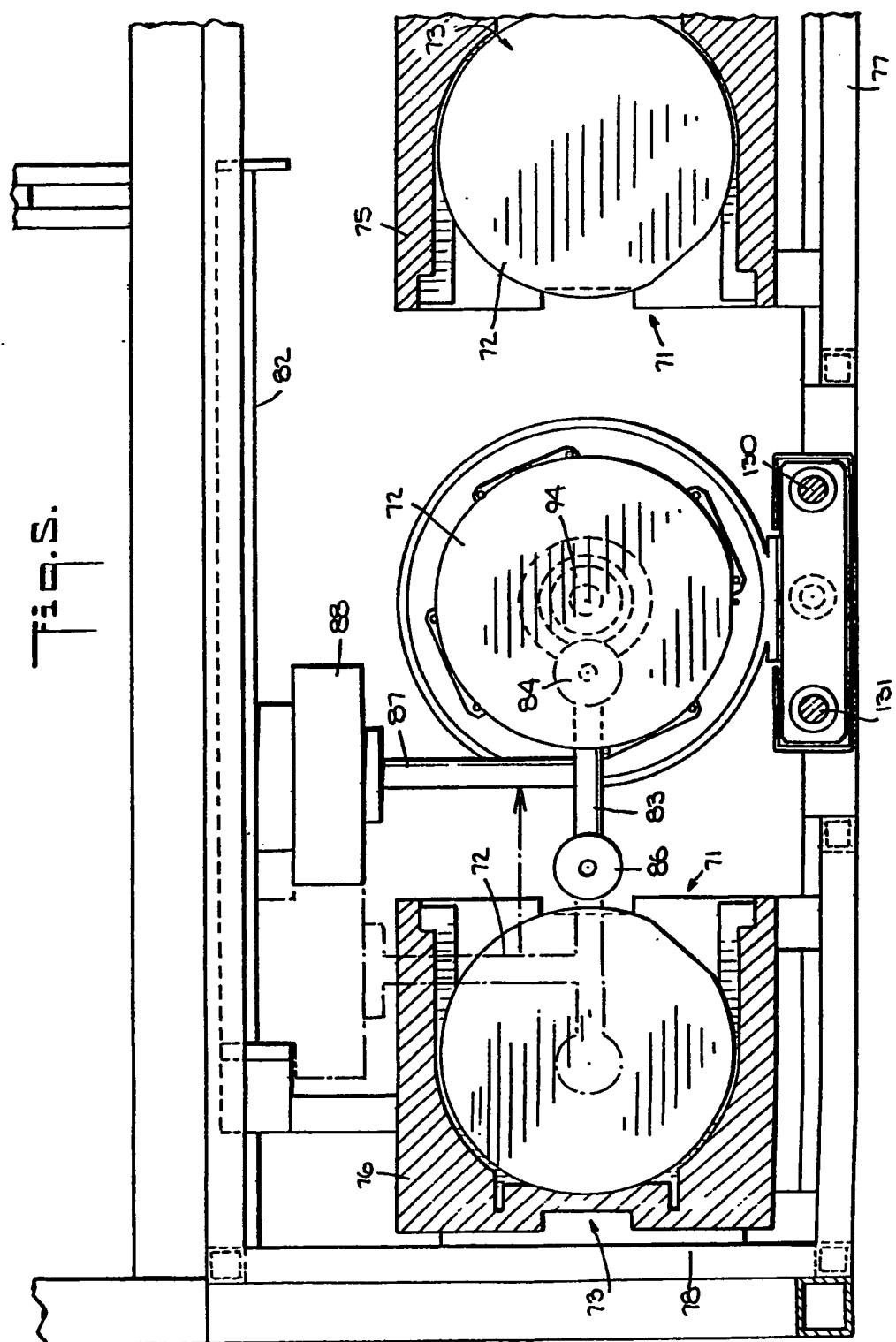
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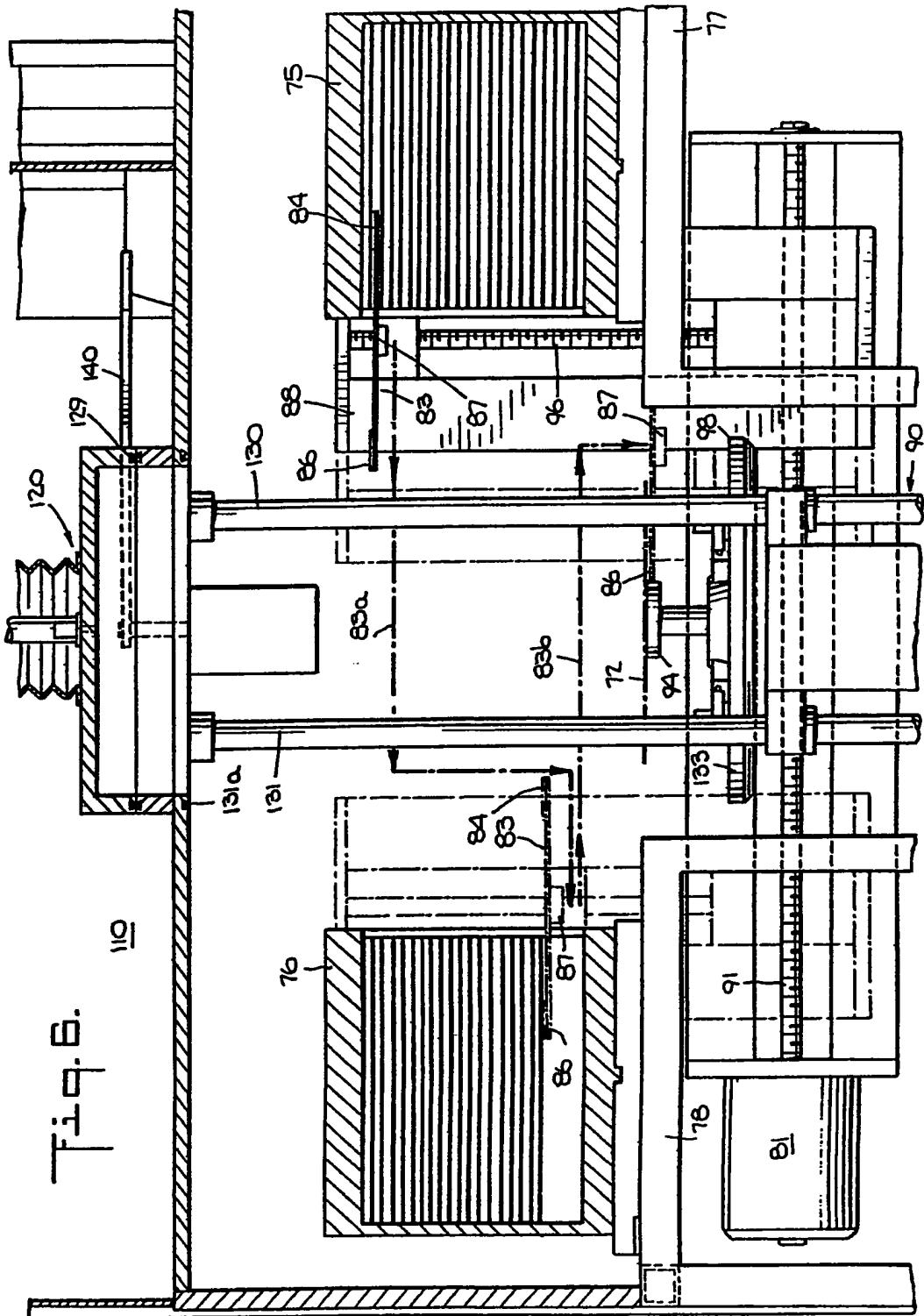
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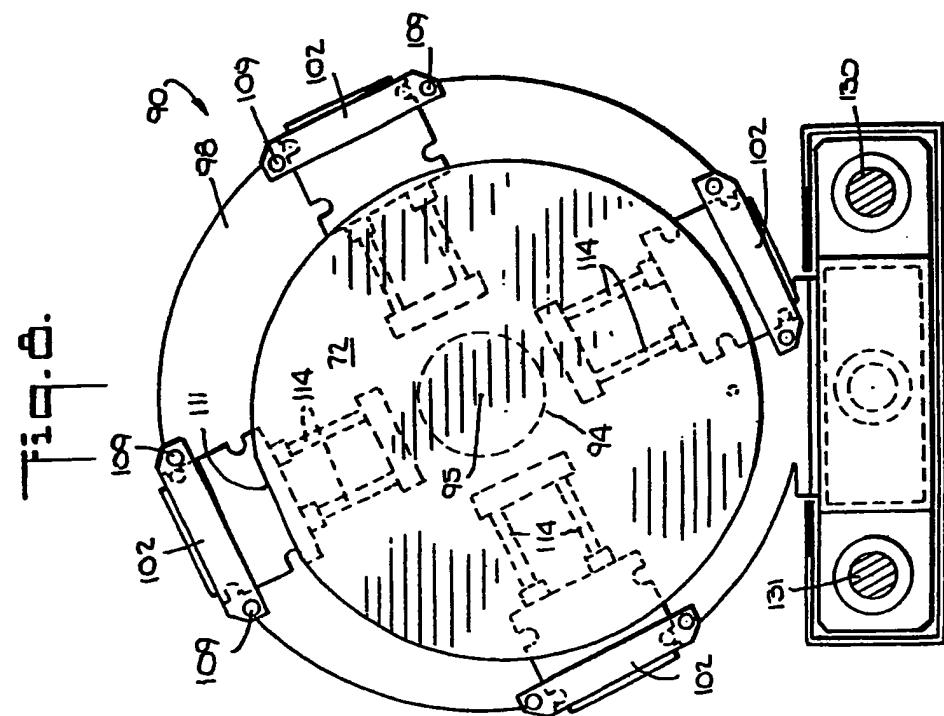
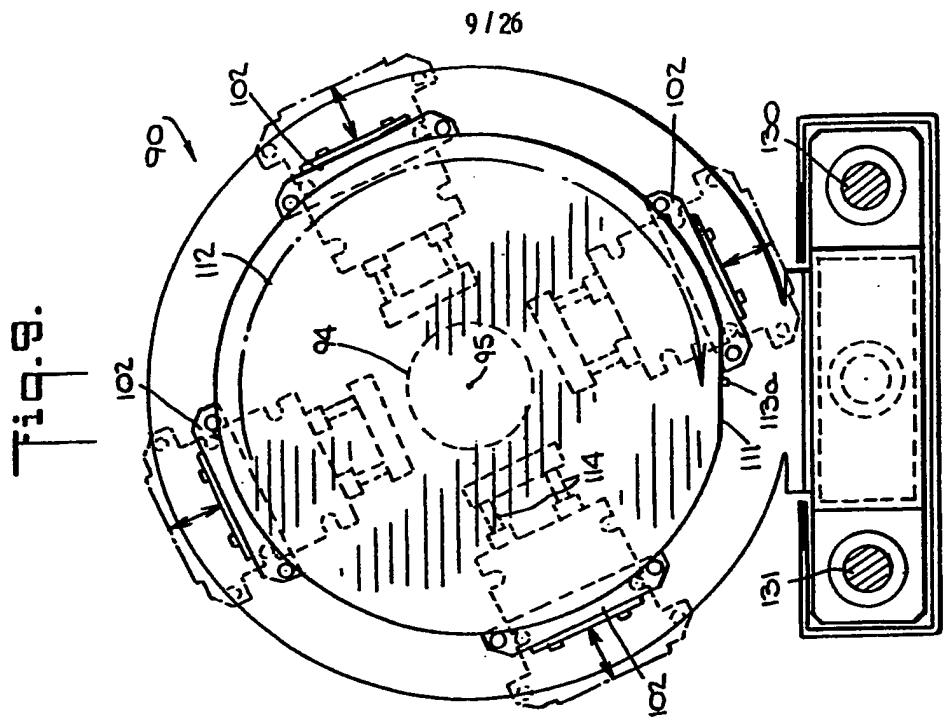
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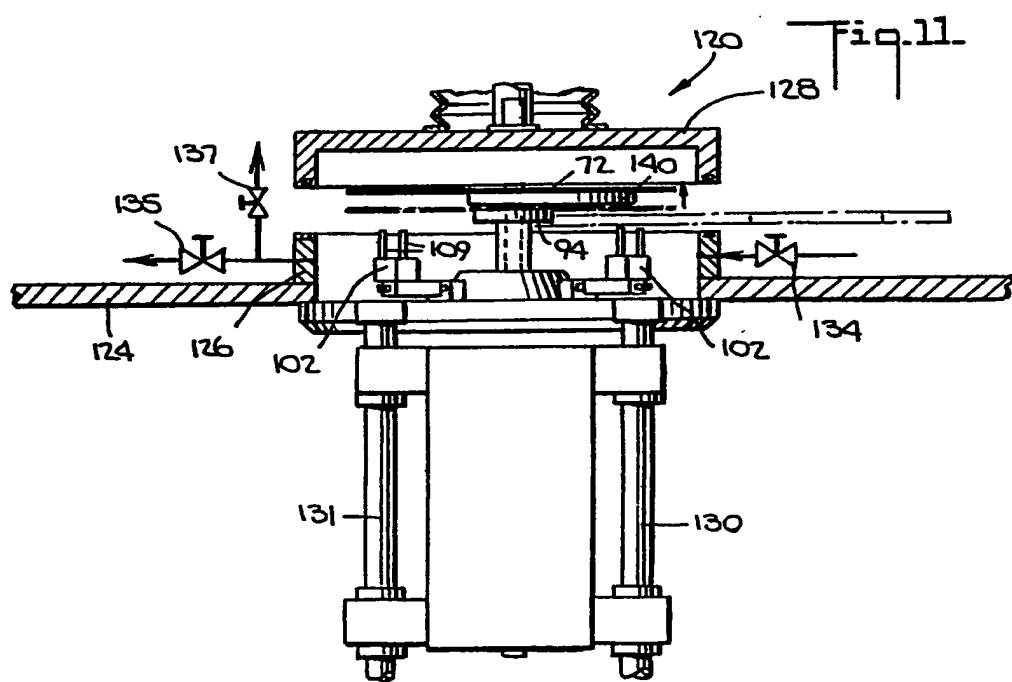
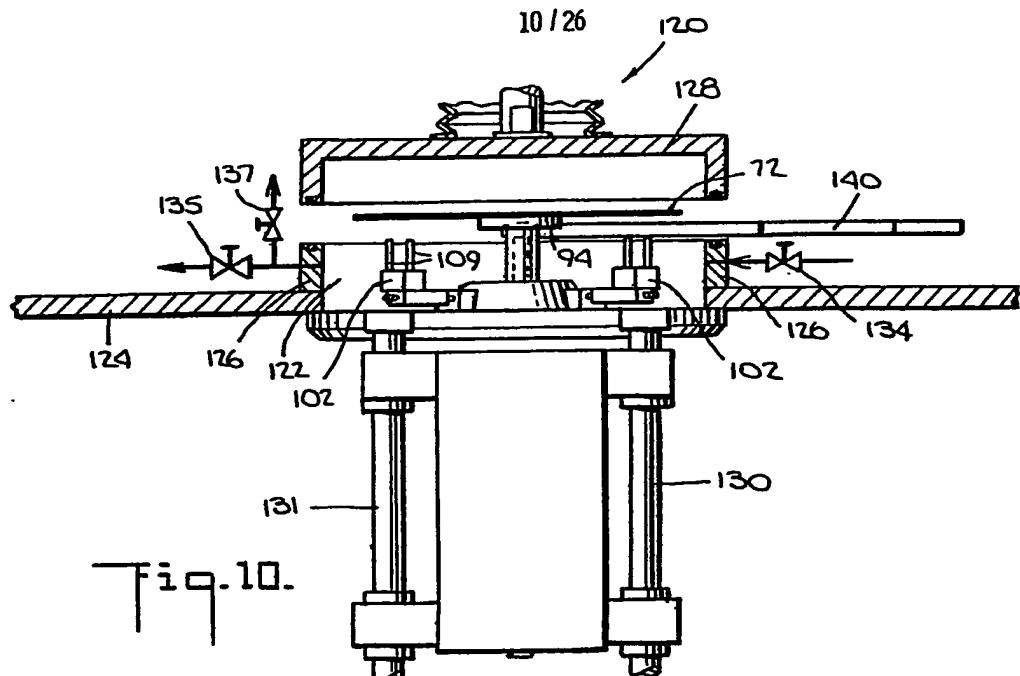


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S. 10

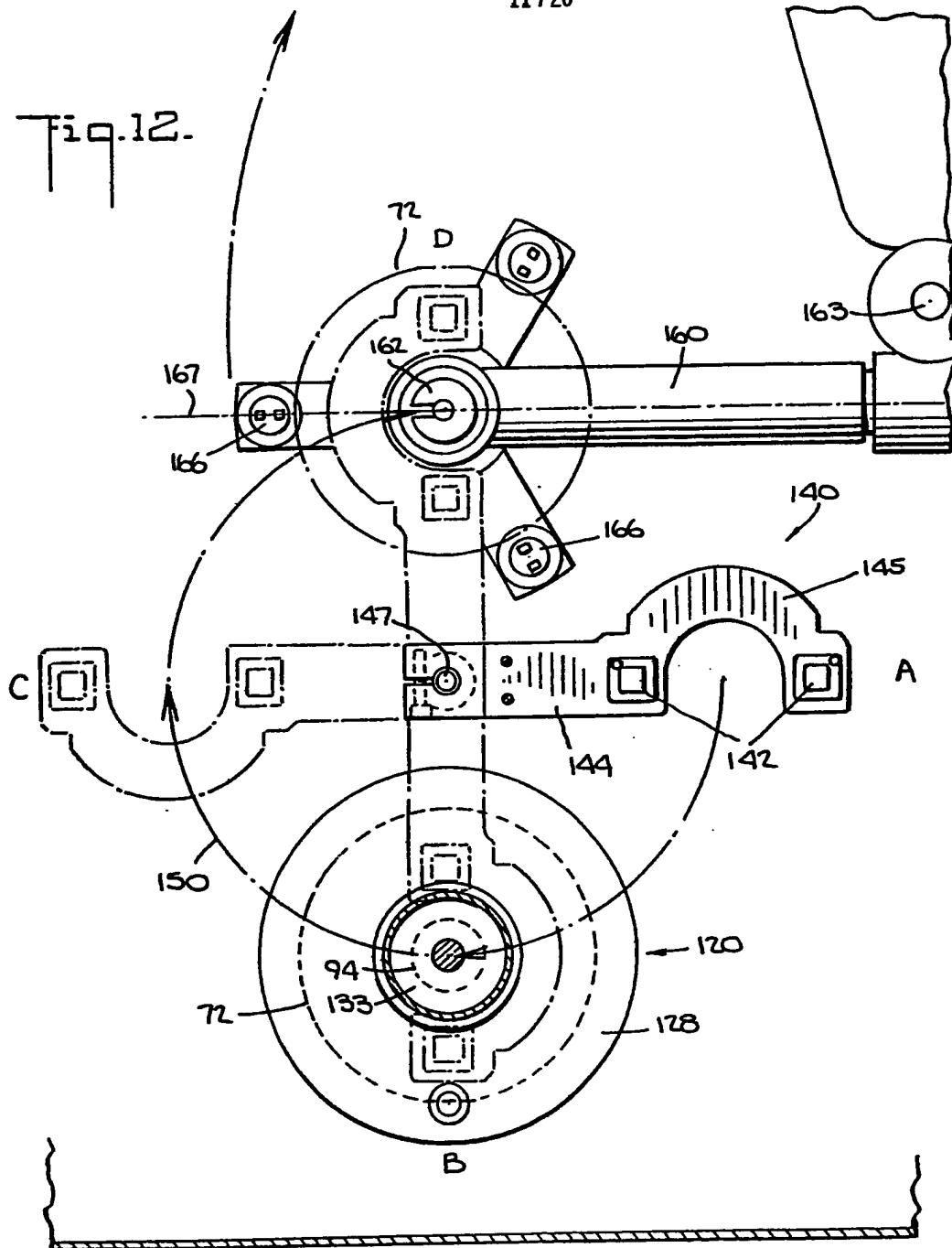


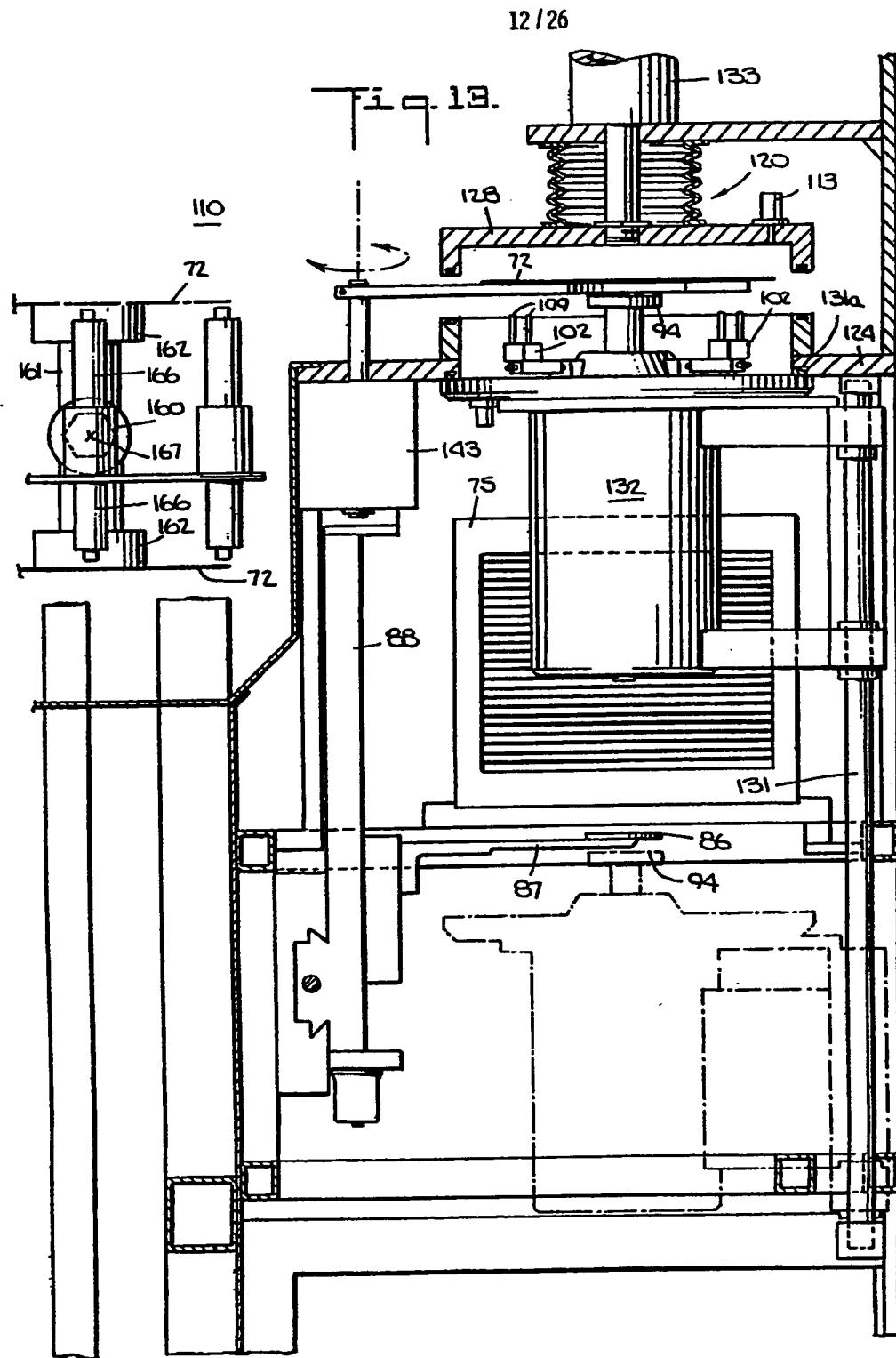
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Patent Office Drawing

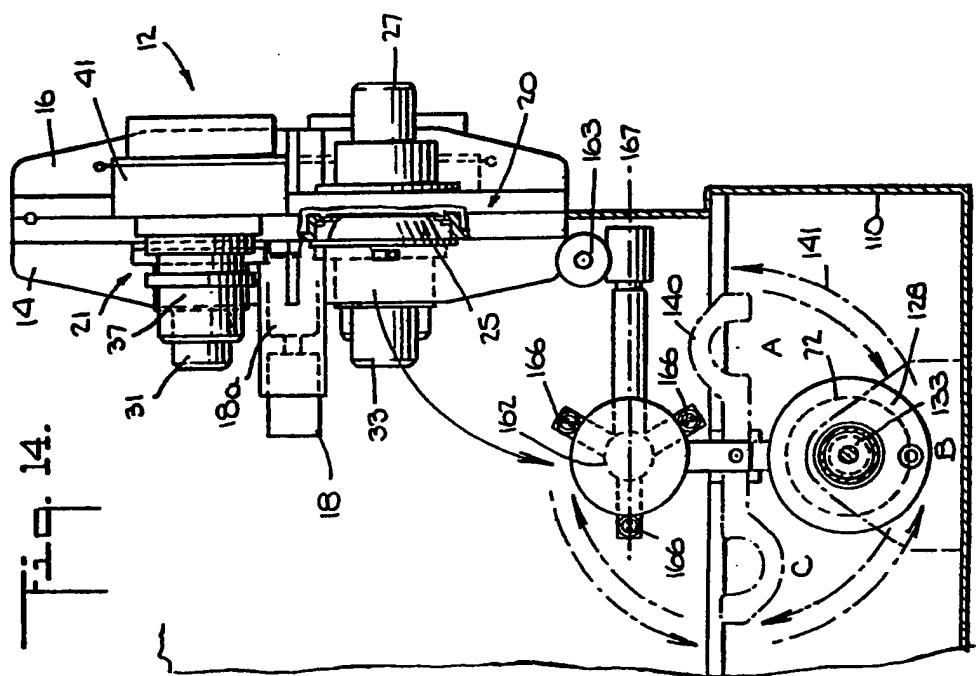
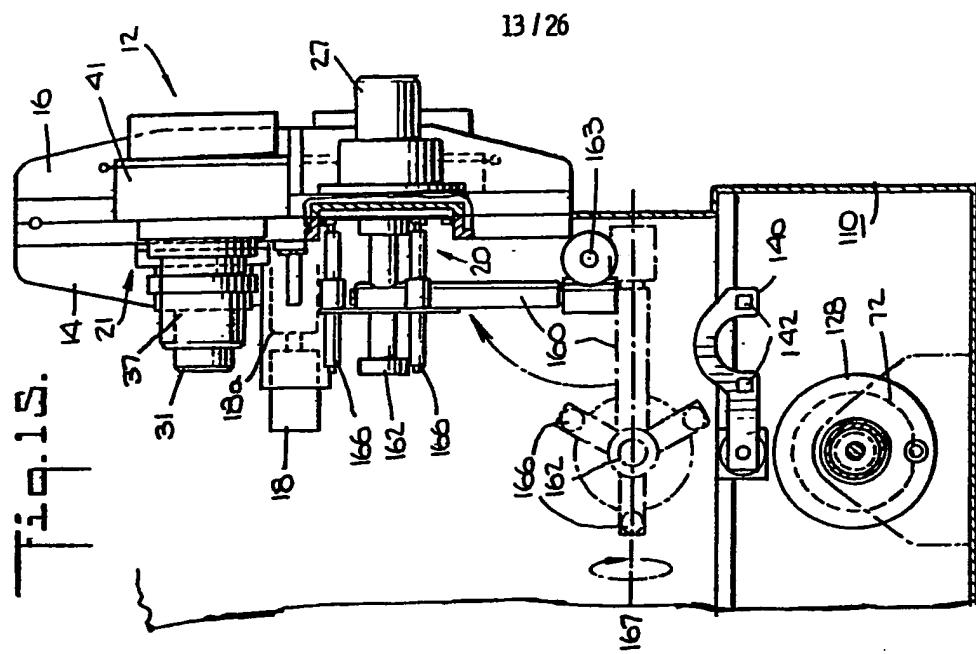
11/26

Fig. 12.



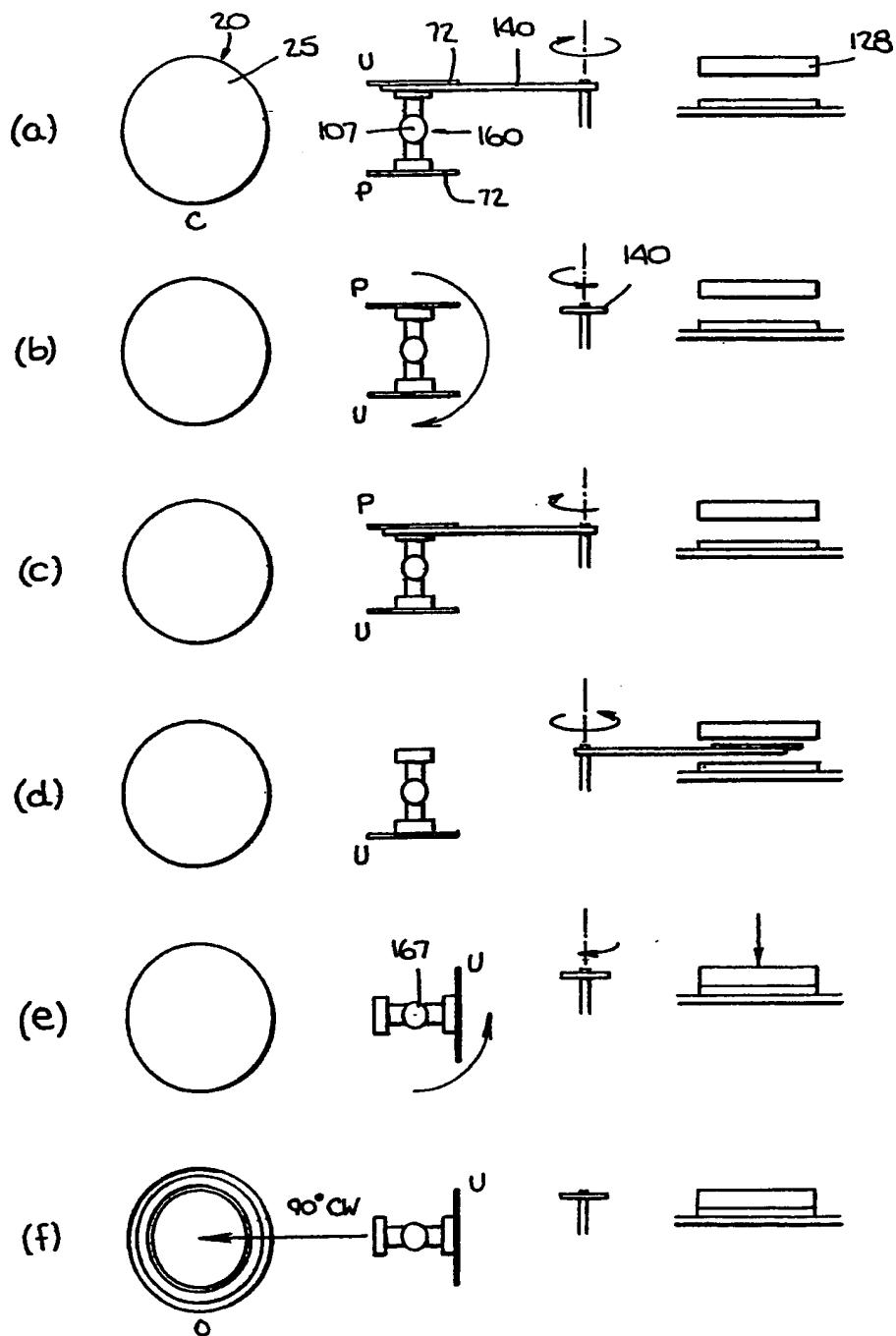


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14/26

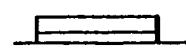
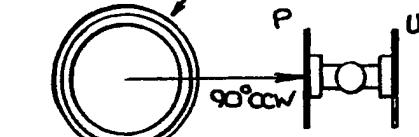
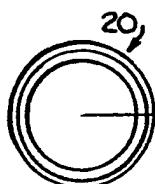
Fig. 15A.



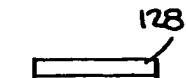
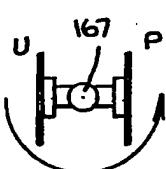
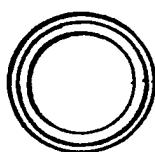
15/26

## Fig. 15B.

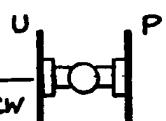
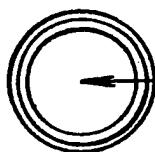
(g)



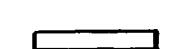
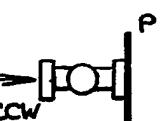
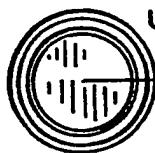
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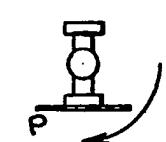
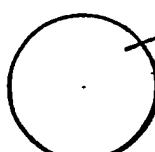
(i)



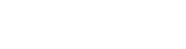
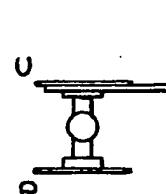
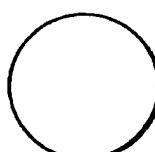
(j)



(k)

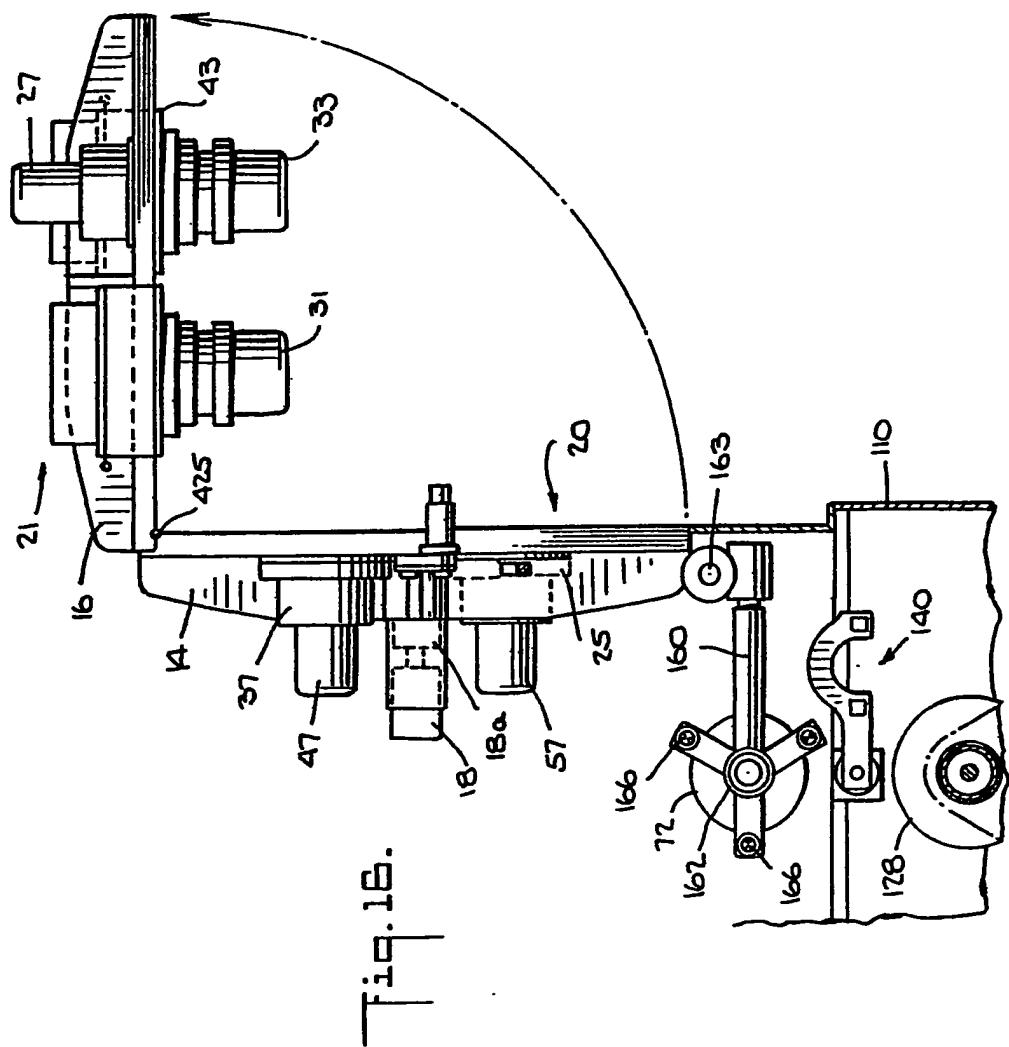


(l)



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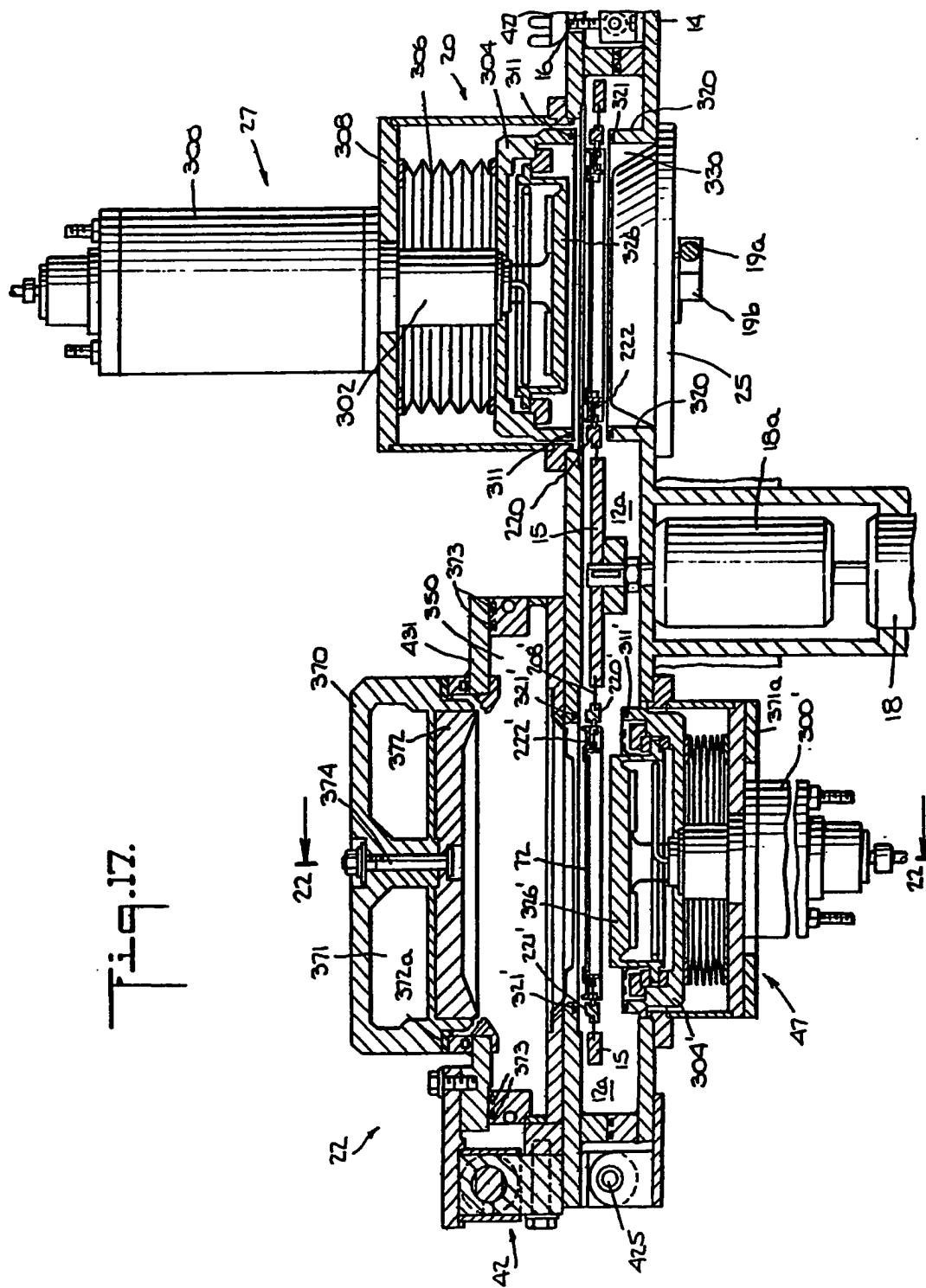
16 / 26



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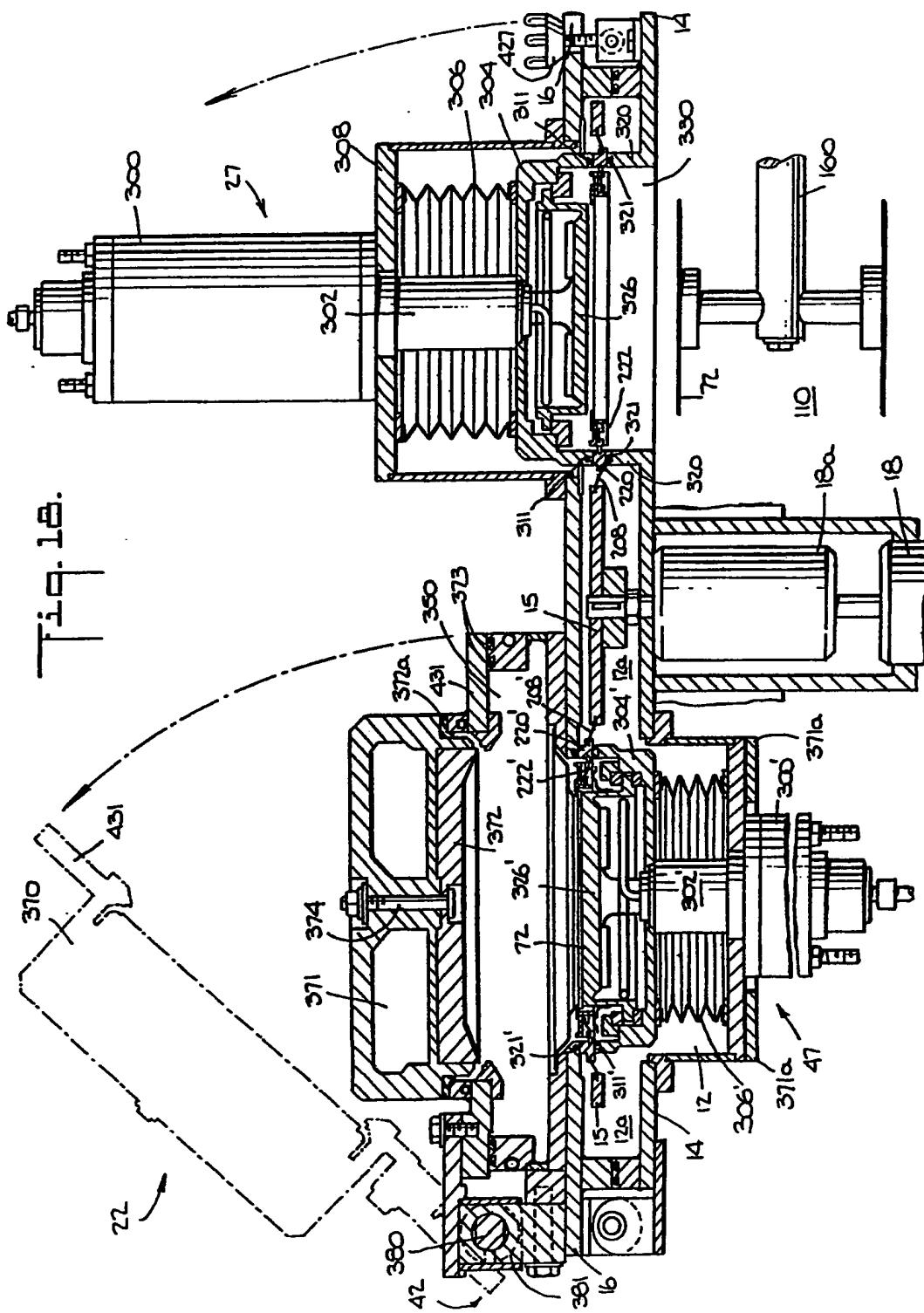
**Nouvellement déposé**

17 / 26



0 244 951

18 / 26

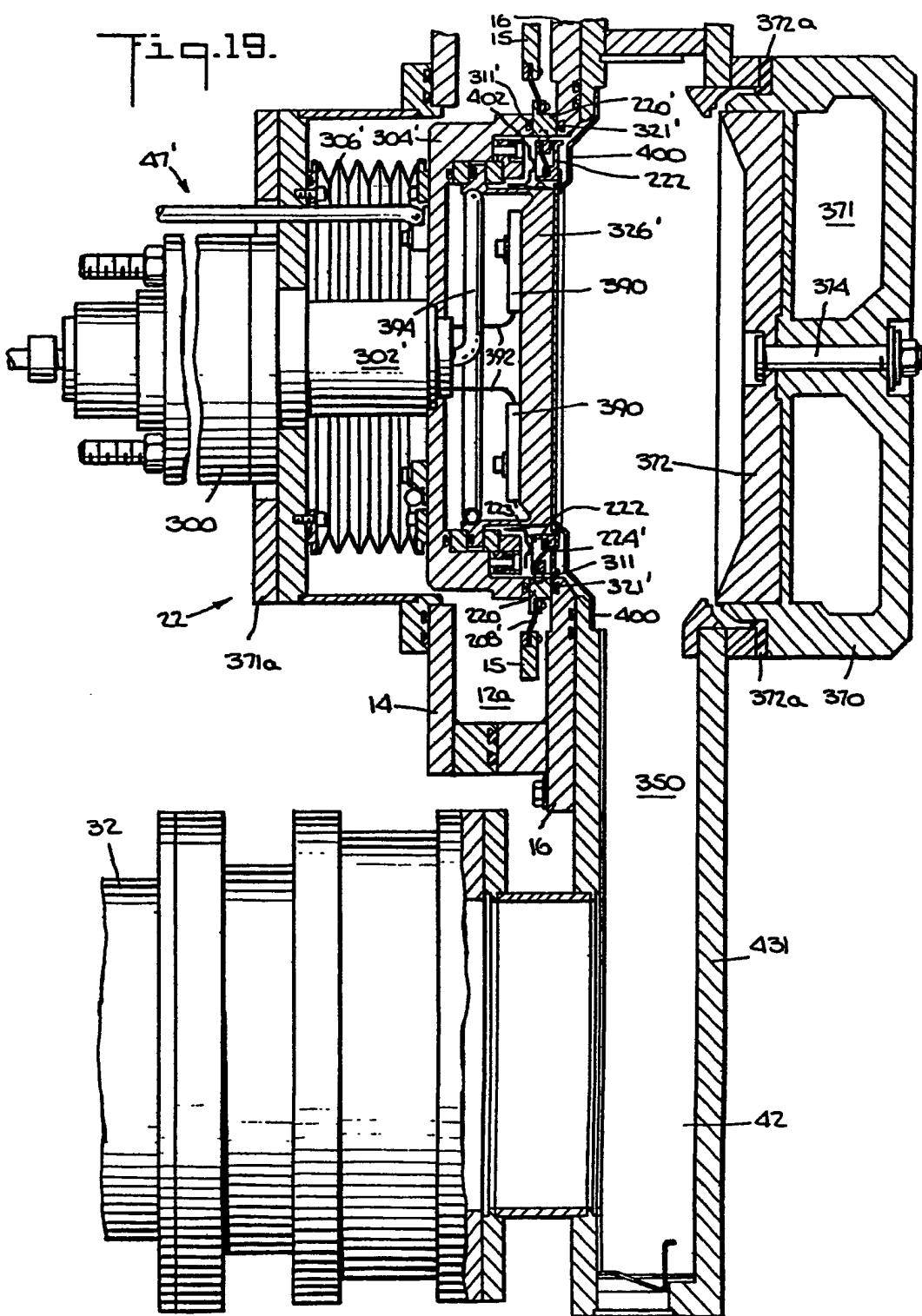


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Key eingereicht / Keyly filed  
Nouvellement déposé

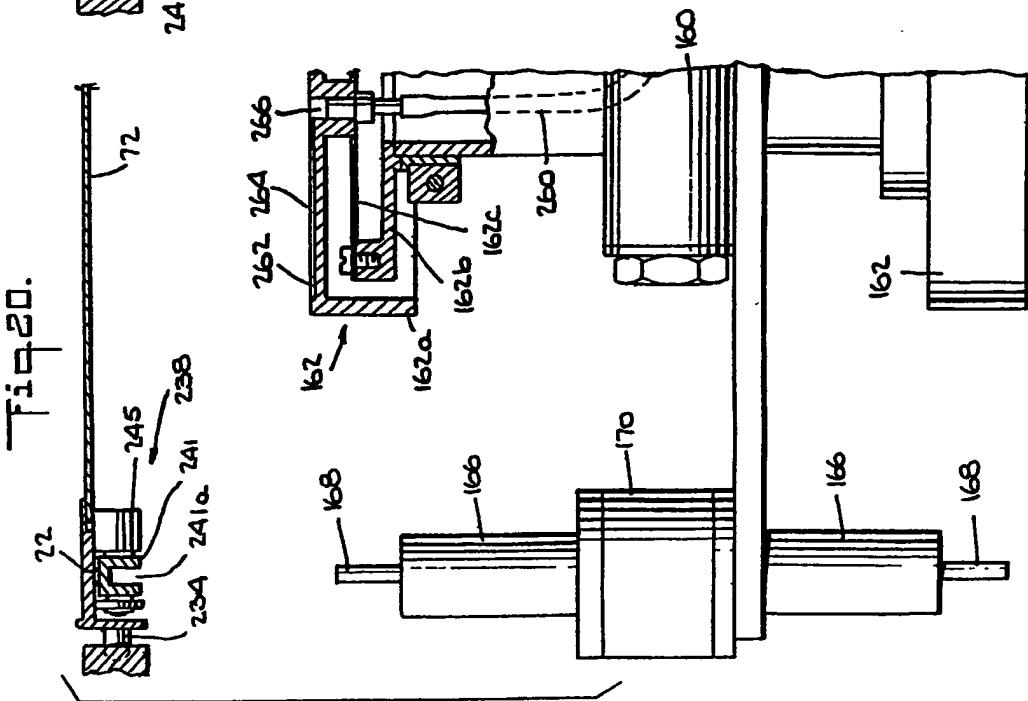
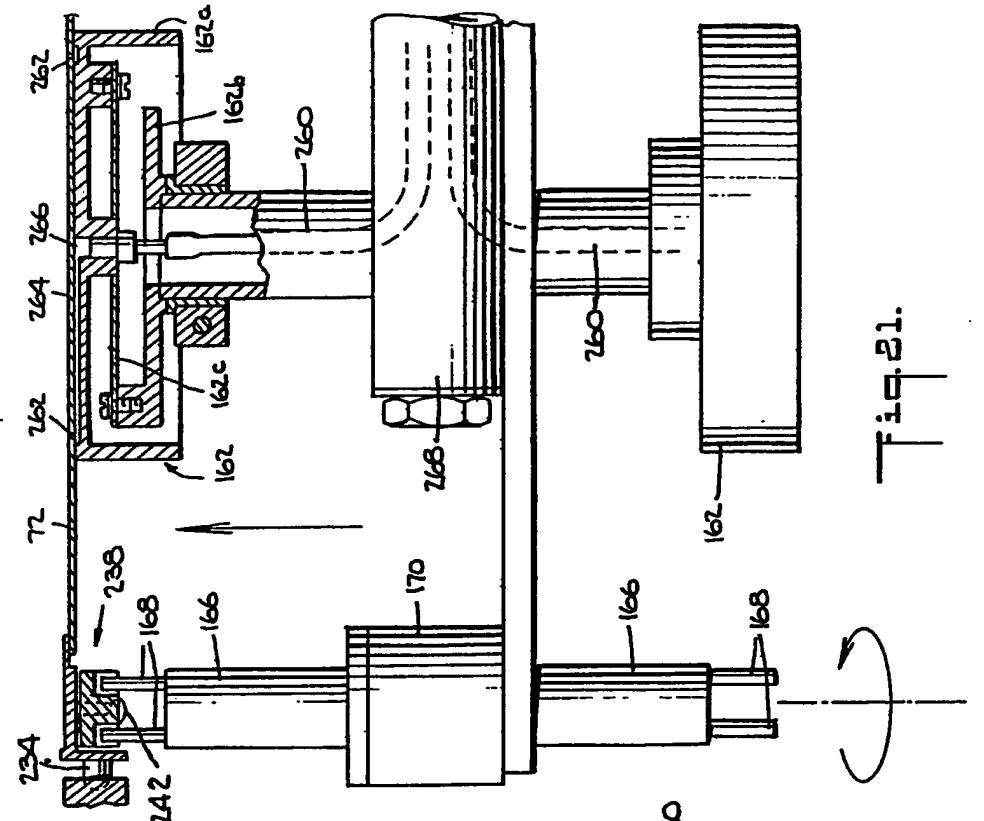
19 / 26

Fig. 19.



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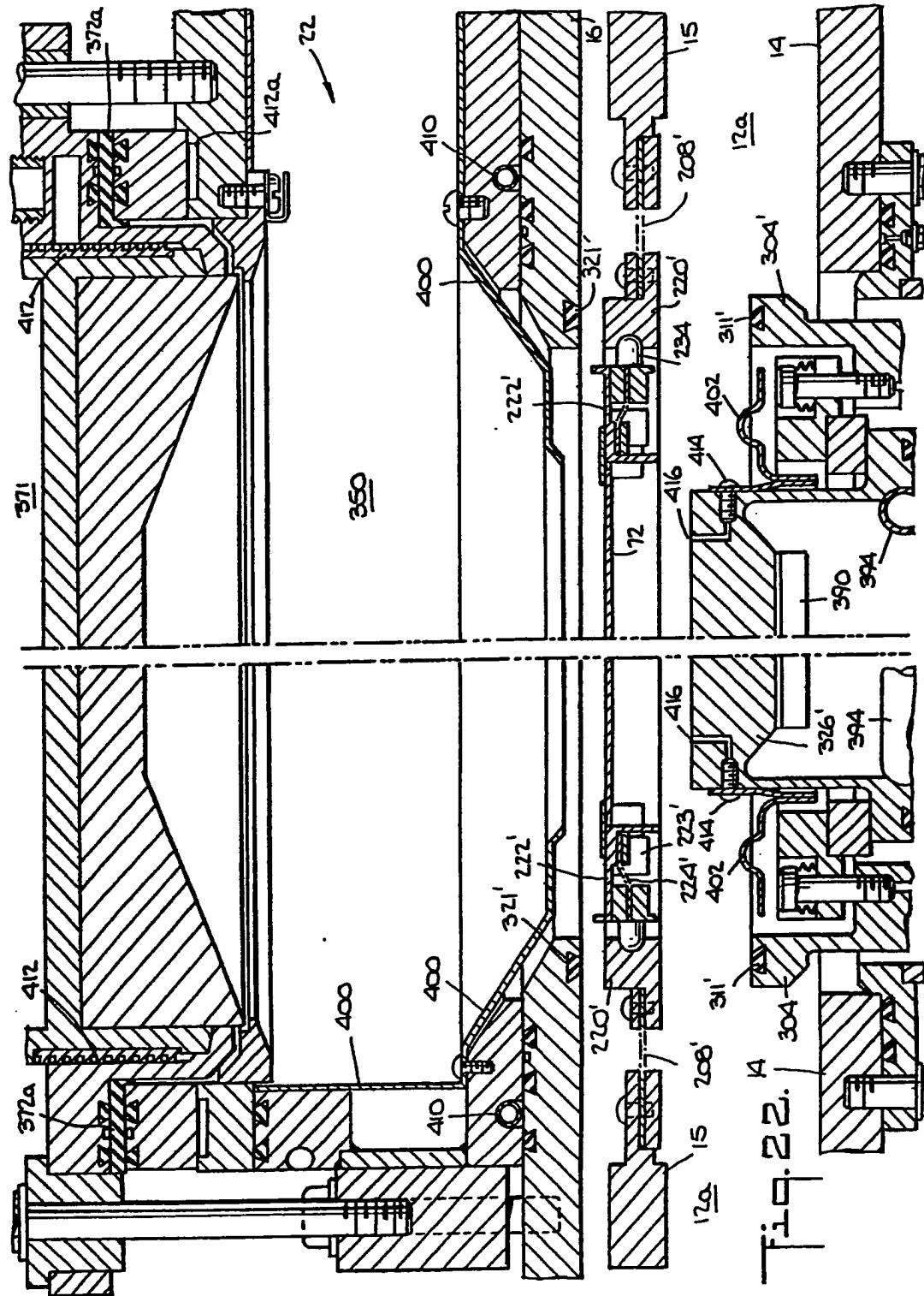
20 / 26



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Montagezeichnung 21/26

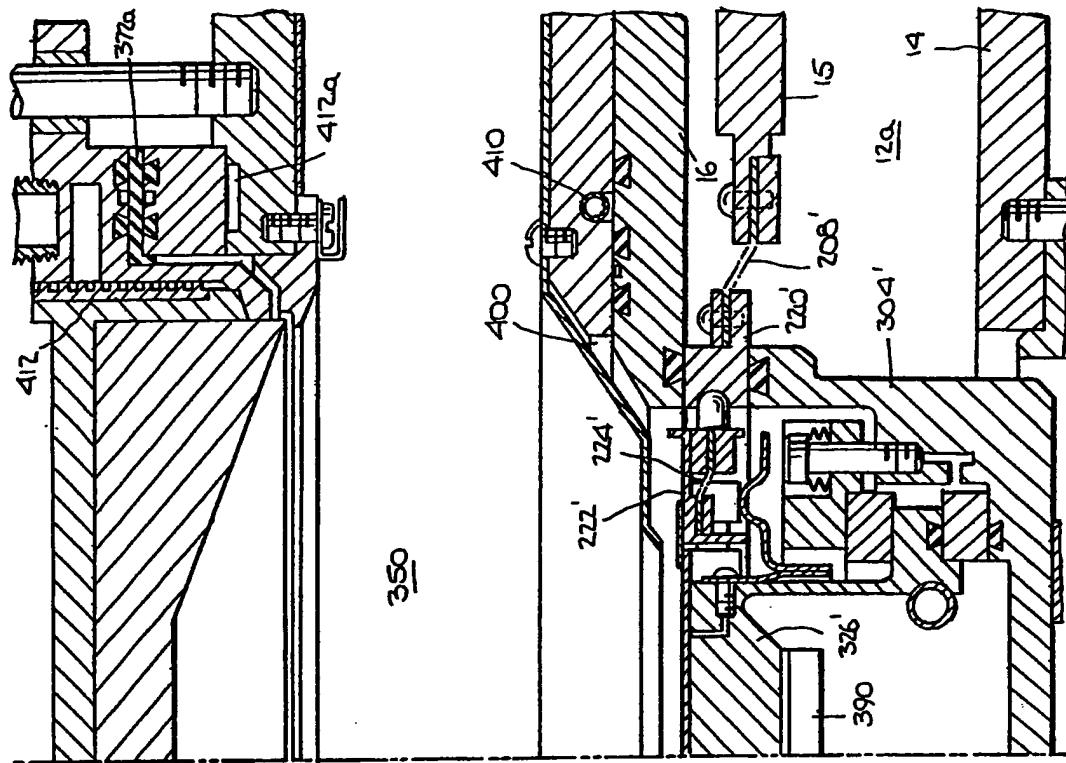
21 / 26



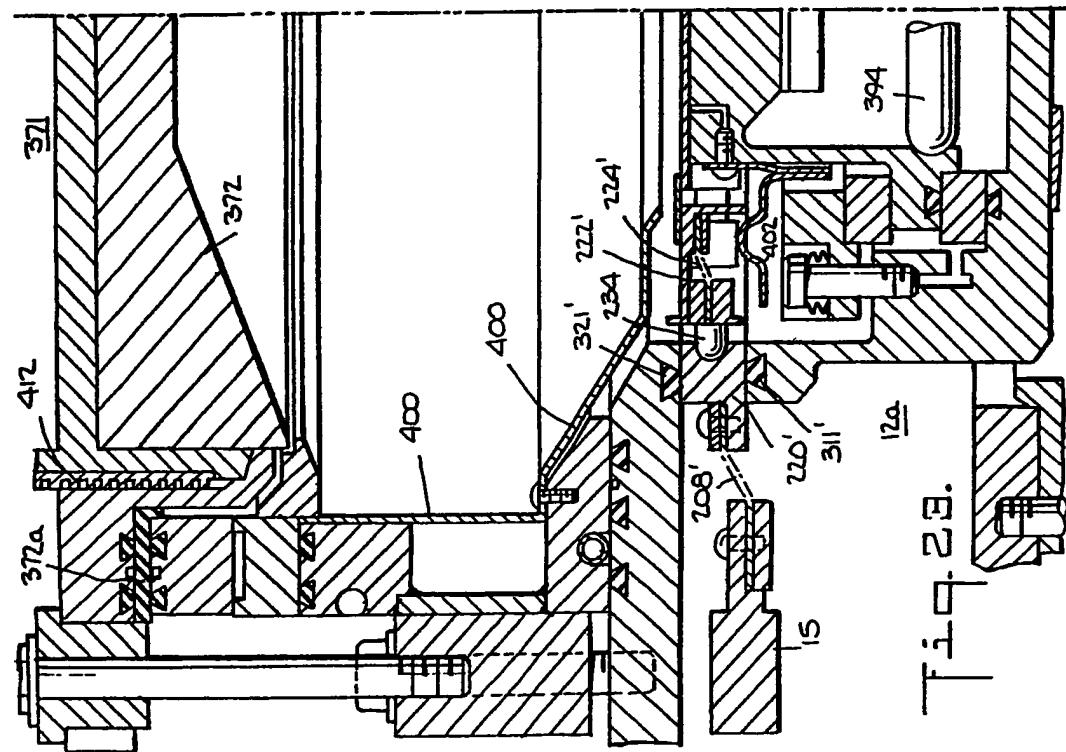
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Novembre 1955

22 126



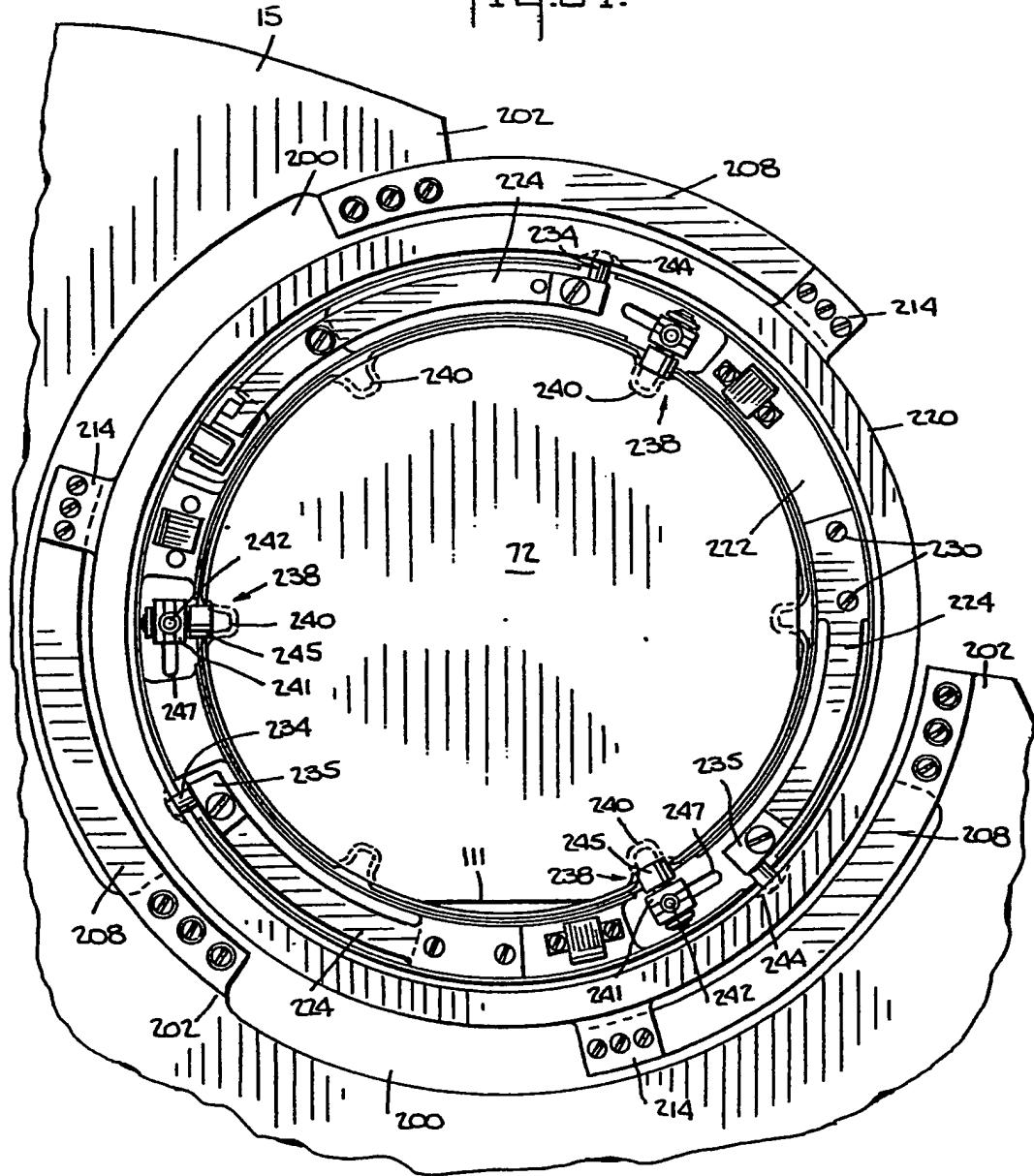
T. 1 - 23.



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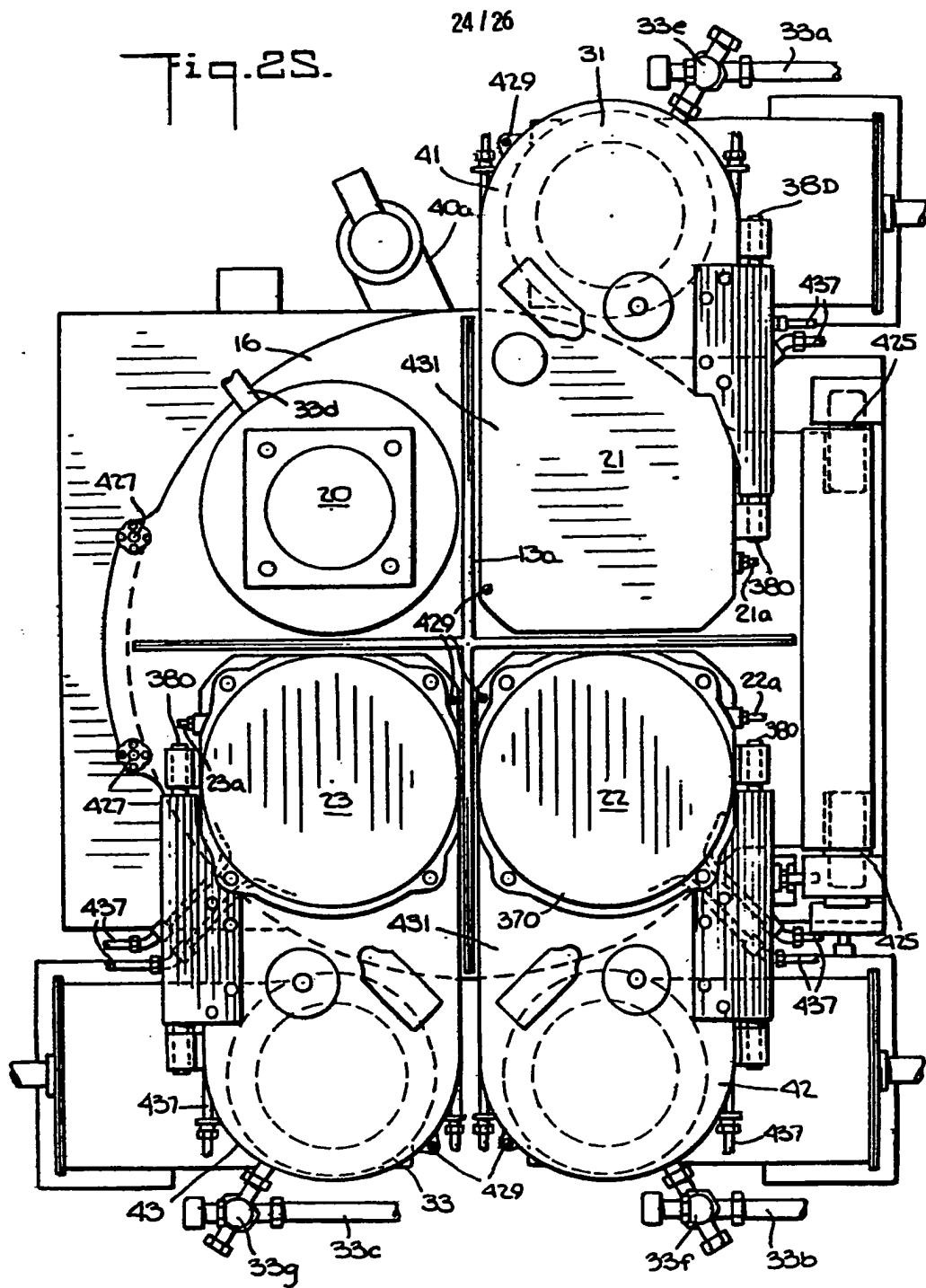
23/26

Fig. 24.



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Fig. 2S.



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Non-volatile memory device

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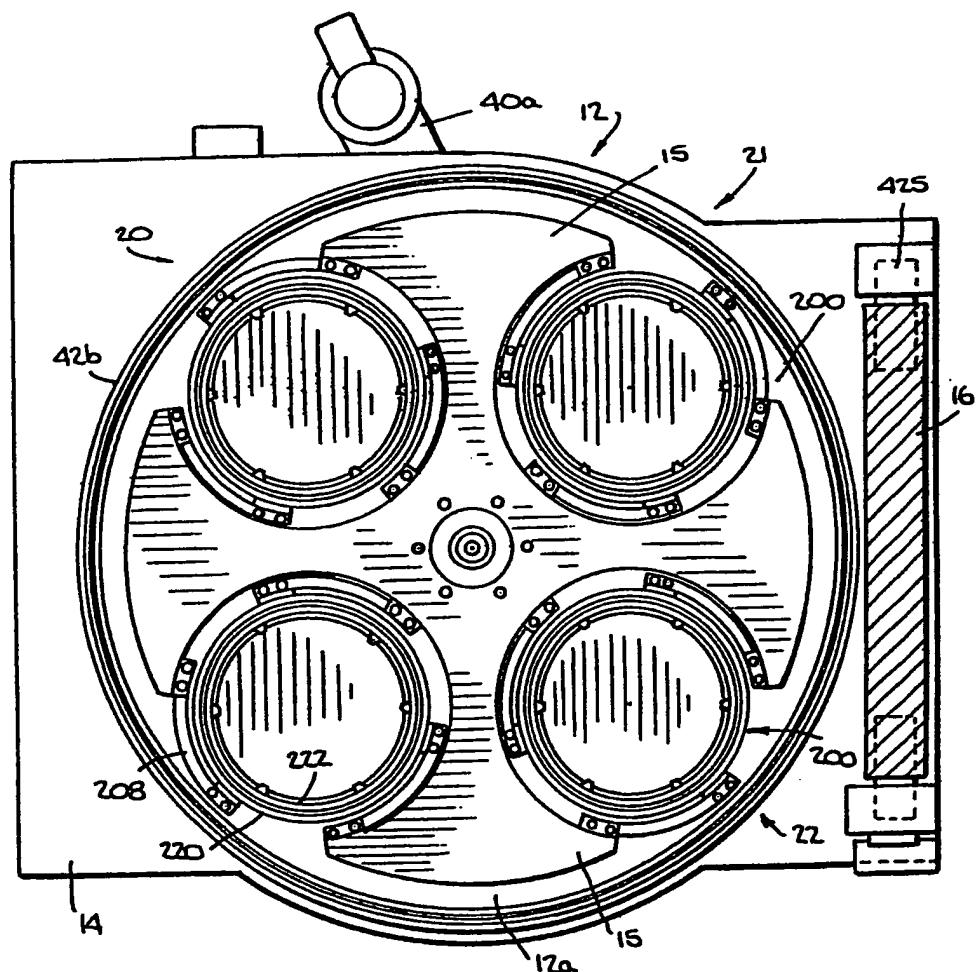


Fig. 26.

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Neu eingereicht / Newly filed  
Nouvellement déposé

